

FIG. 1A

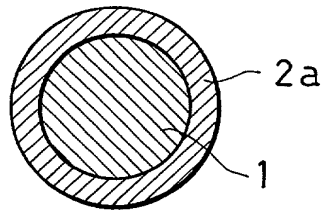


FIG. 1B

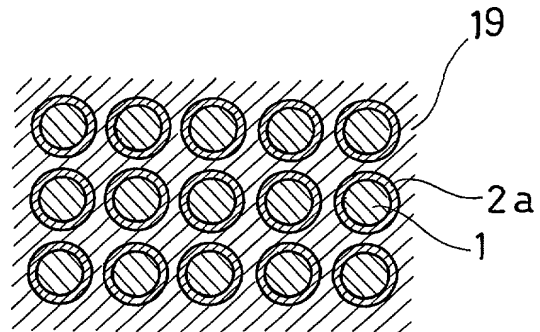


FIG. 1C

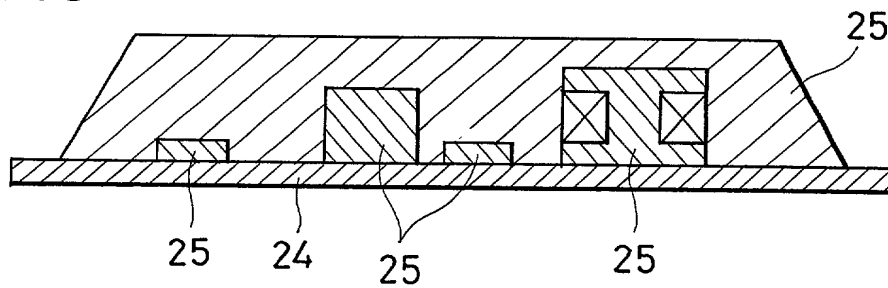


FIG. 1D

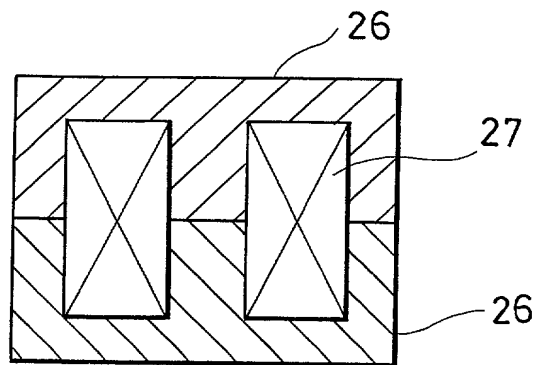
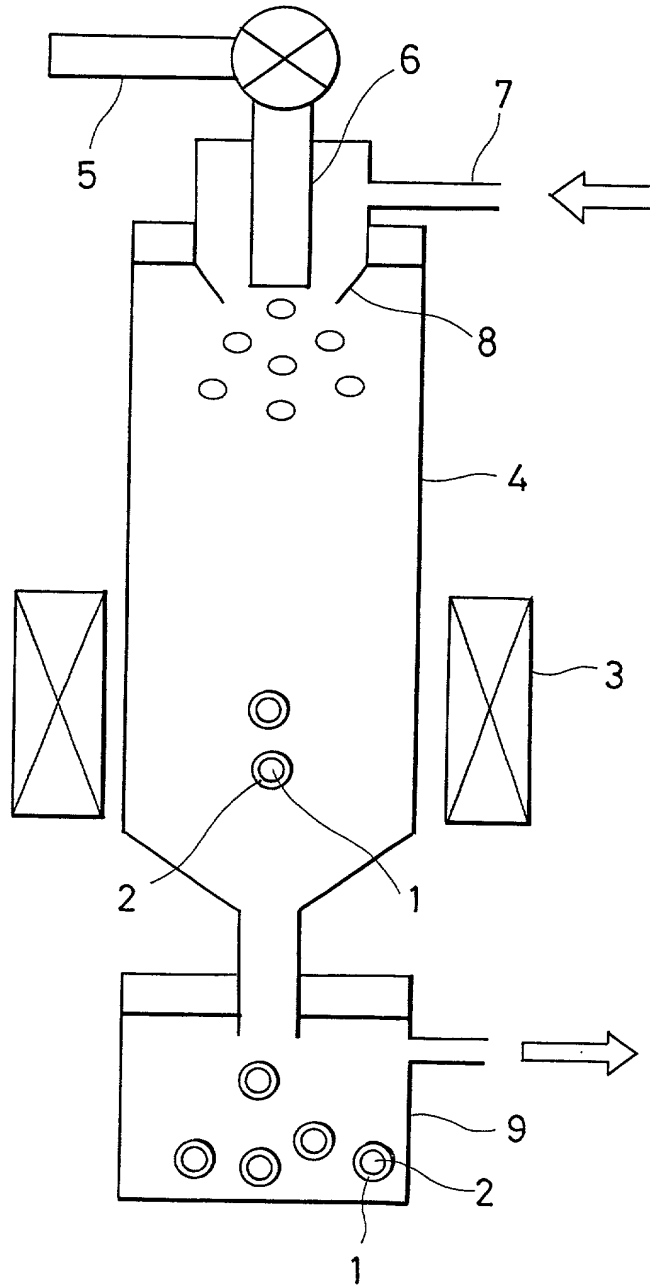


FIG. 2



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FIG. 3A

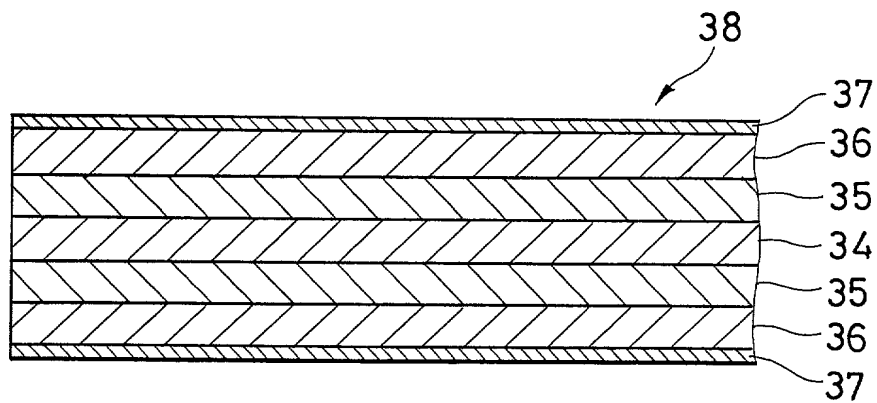


FIG. 3B



FIG. 4A

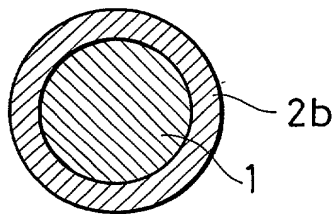


FIG. 4B

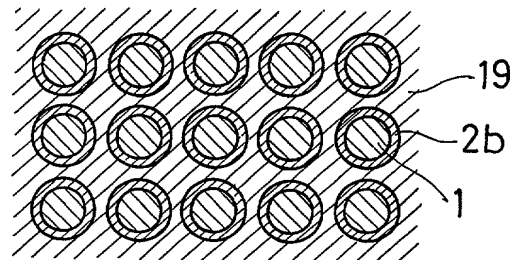


FIG. 4C

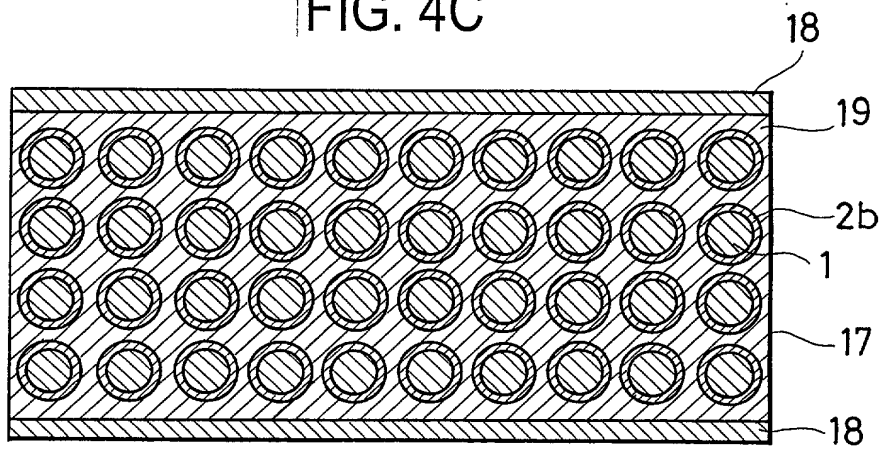
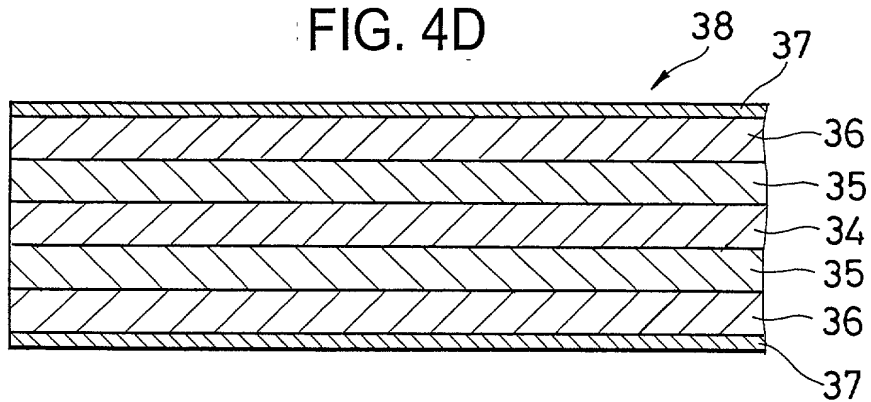


FIG. 4D



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FIG. 5A

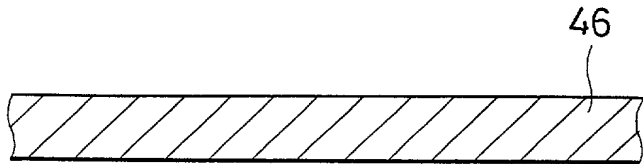


FIG. 5B

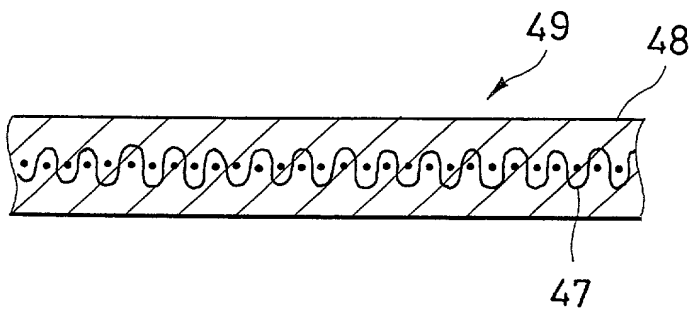


FIG. 5C

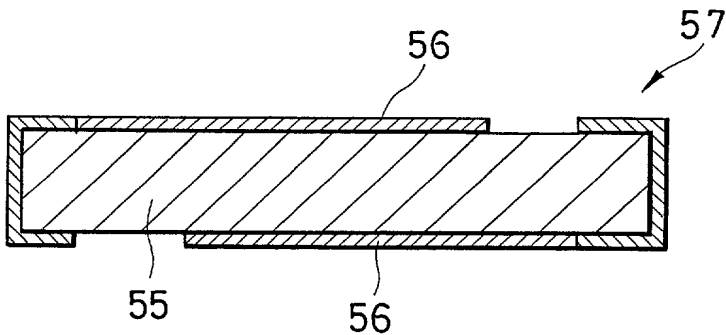


FIG. 5D

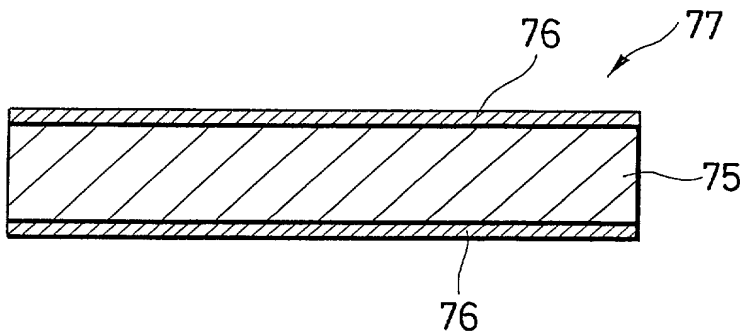
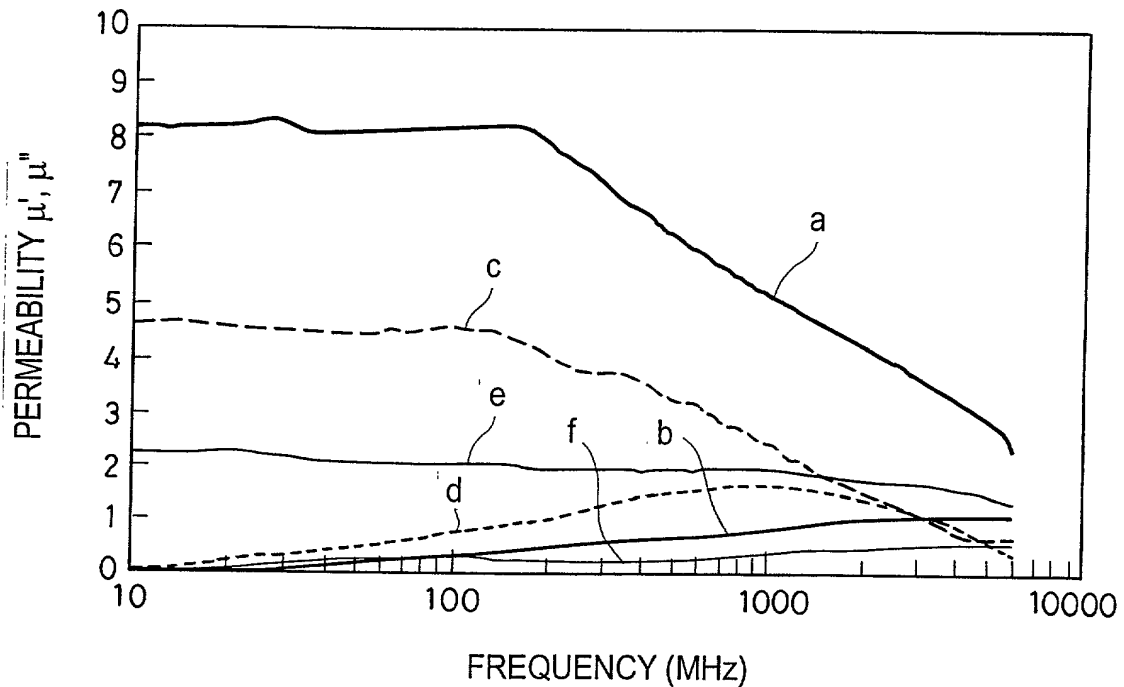
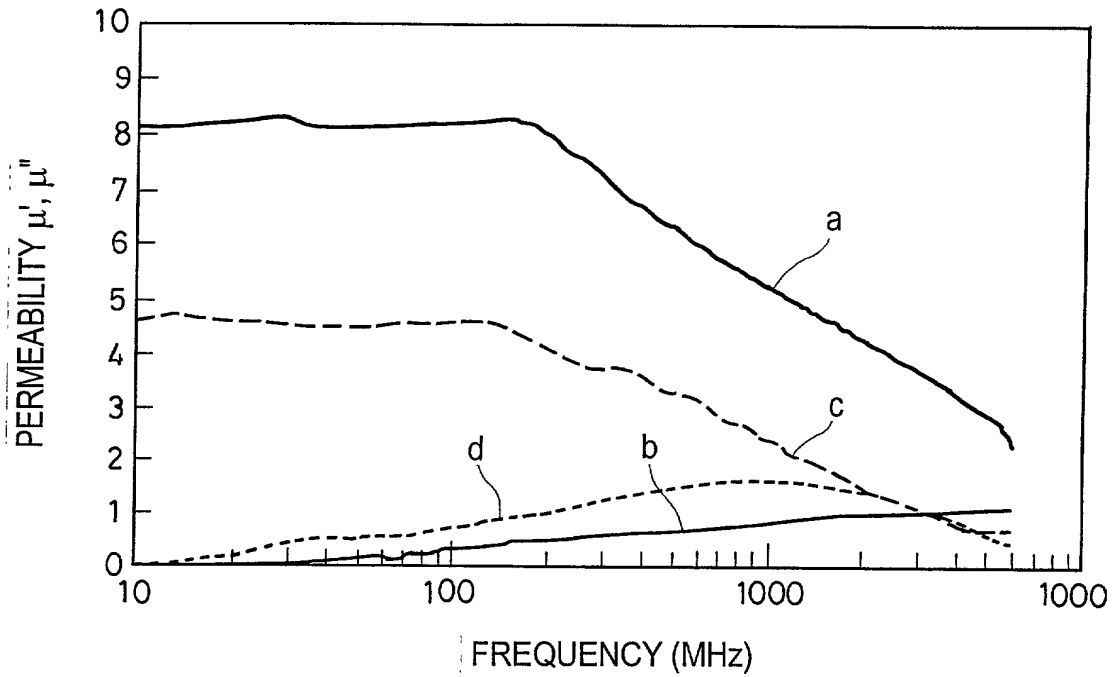


FIG. 6



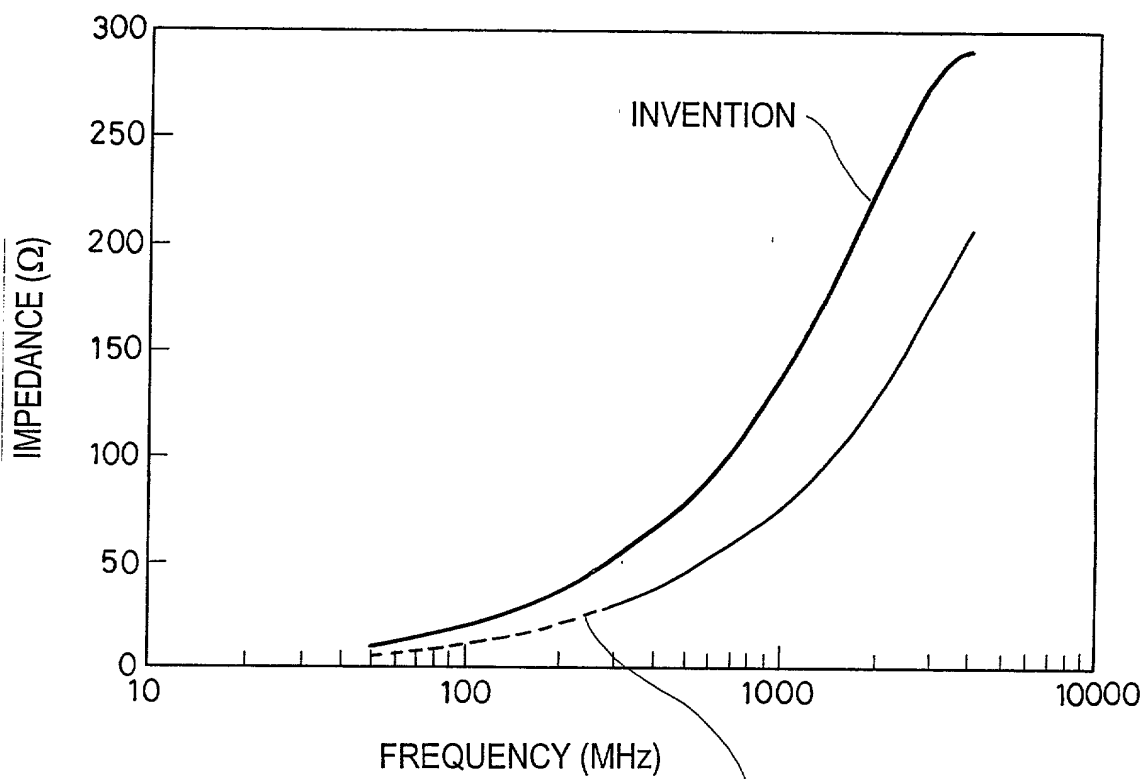
- a: INVENTION, μ'
BARIUM TITANATE-COATED IRON POWDER COMPOSITE MATERIAL
- b: INVENTION, μ''
BARIUM TITANATE-COATED IRON POWDER COMPOSITE MATERIAL
- c: COMPARISON 1, μ'
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL
- d: COMPARISON 1, μ''
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL
- e: COMPARISON 2, μ'
LOW-PERMEABILITY FERRITE COMPOSITE MATERIAL
- f: COMPARISON 2, μ''
LOW-PERMEABILITY FERRITE COMPOSITE MATERIAL

FIG. 7



- a: INVENTION, μ'
GLASS-COATED IRON POWDER COMPOSITE MATERIAL
- b: INVENTION, μ''
GLASS-COATED IRON POWDER COMPOSITE MATERIAL
- c: COMPARISON 1, μ'
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL
- d: COMPARISON 1, μ''
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL

FIG. 8



COMPARISON (HIGH-FREQUENCY BEADS USING FERRITE
COMPOSITE MAGNETIC SUBSTRATE)

FIG. 9

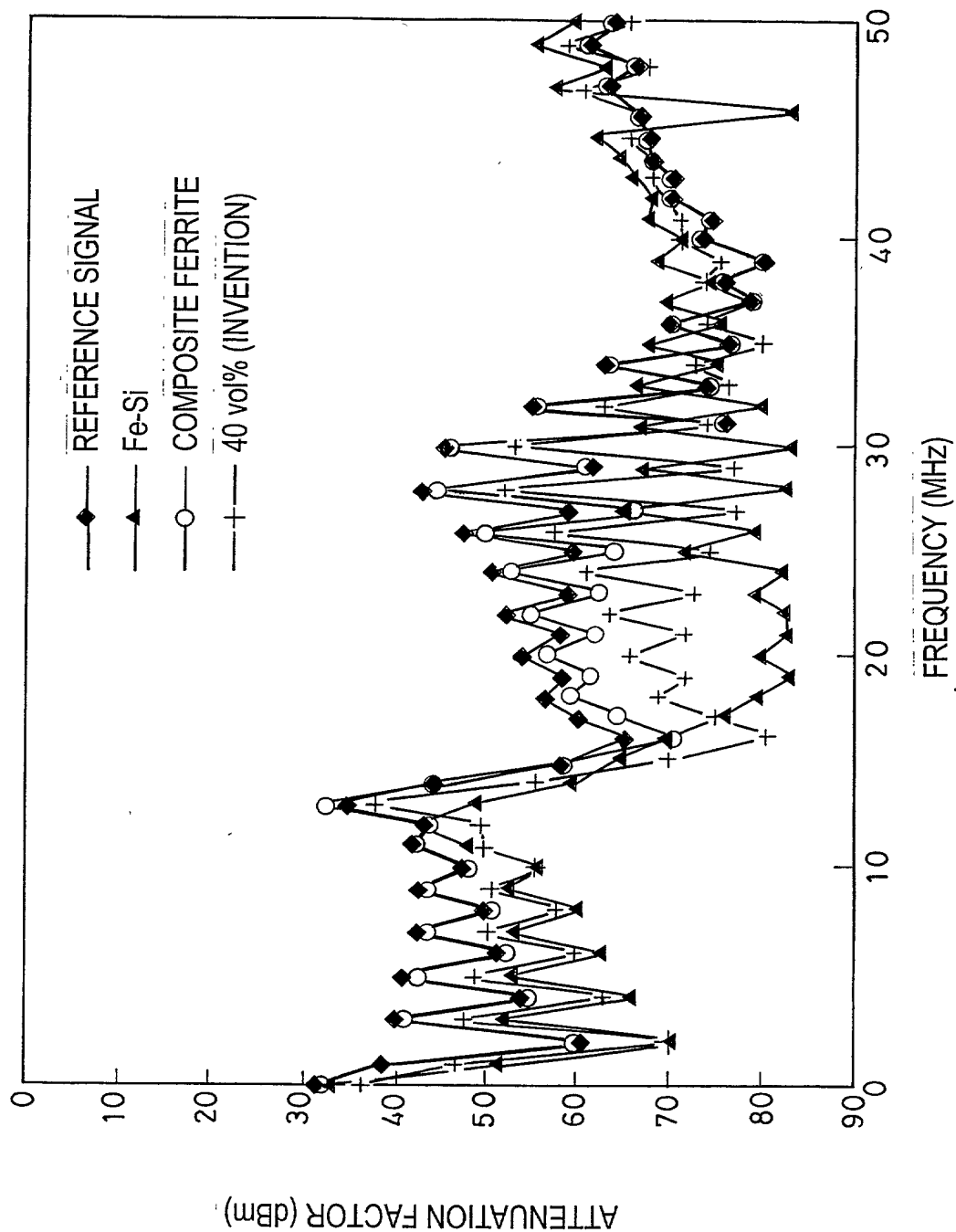


FIG. 10

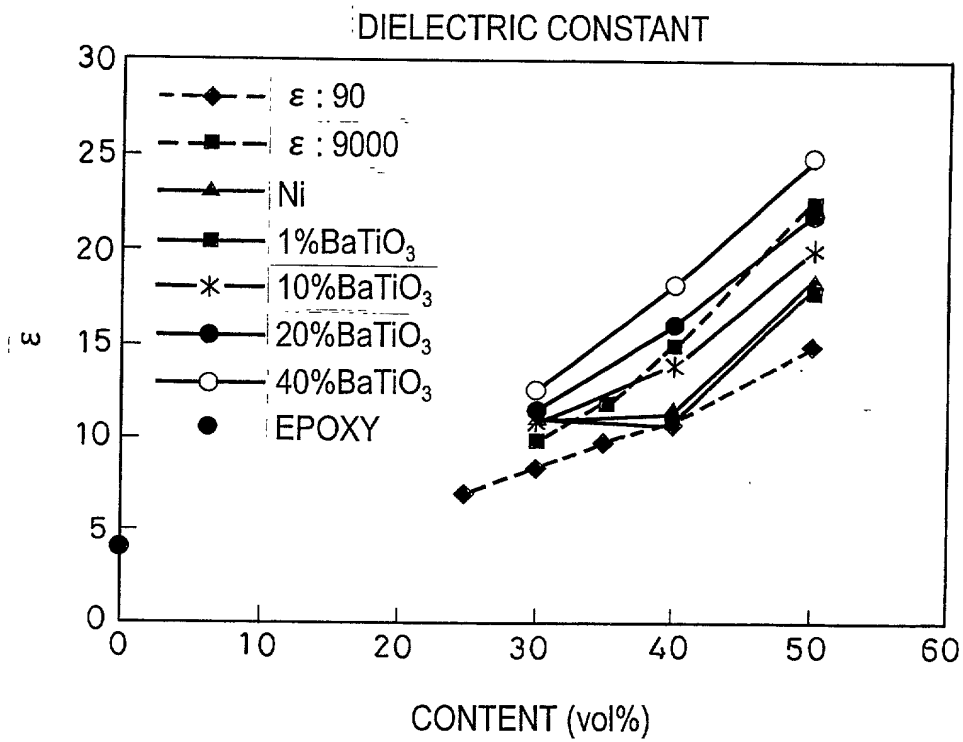


FIG. 11

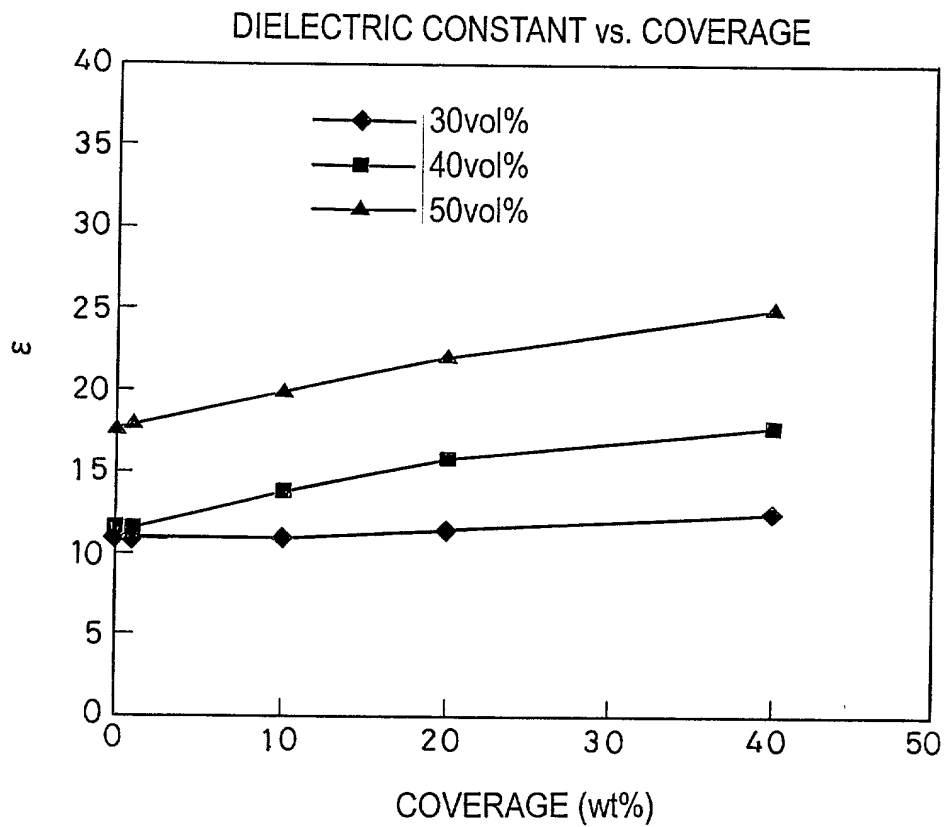


FIG. 12

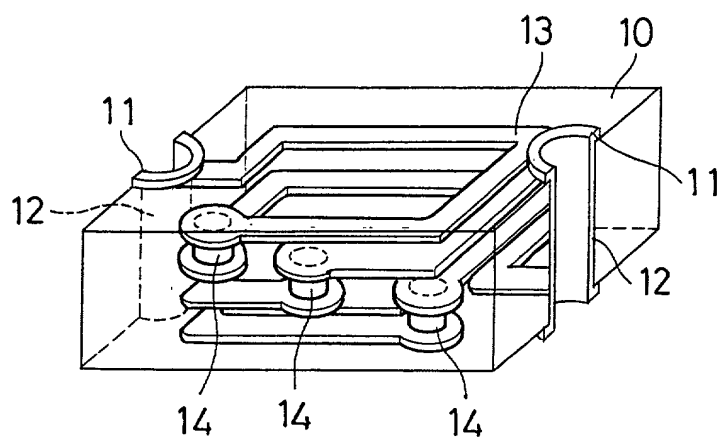


FIG. 13

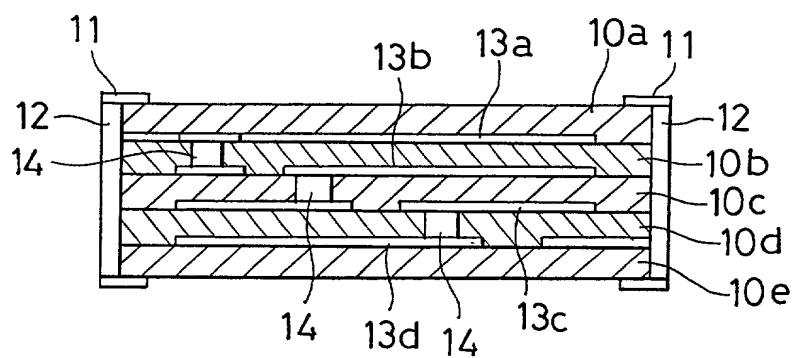


FIG. 14

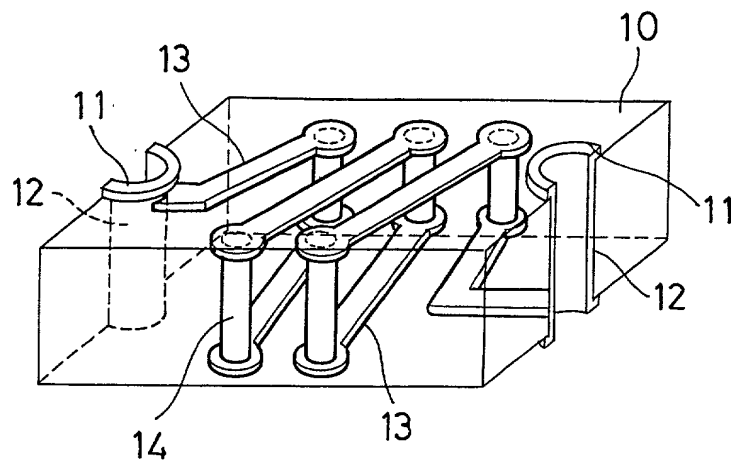


FIG. 15

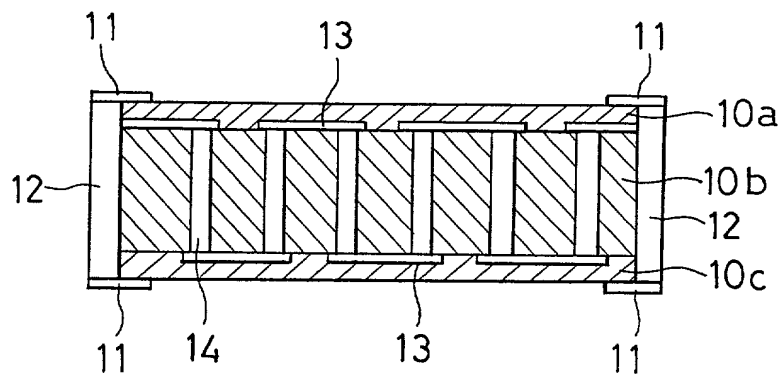


FIG. 17

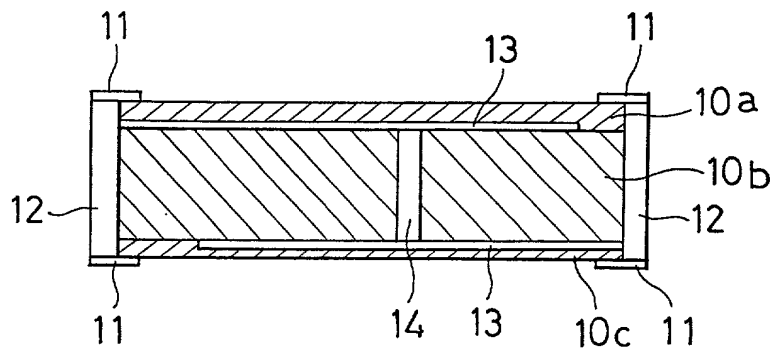


FIG. 18

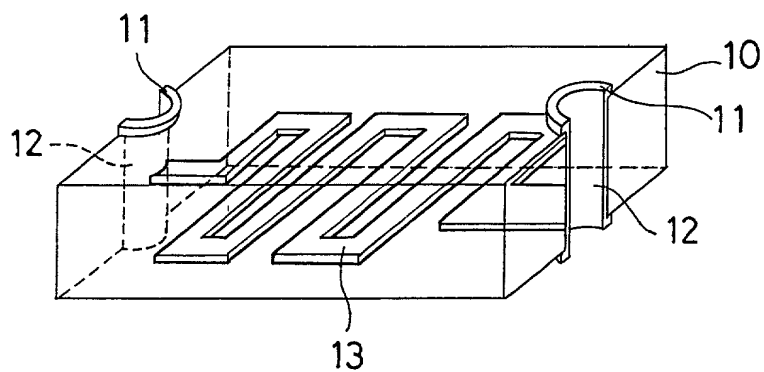


FIG. 19

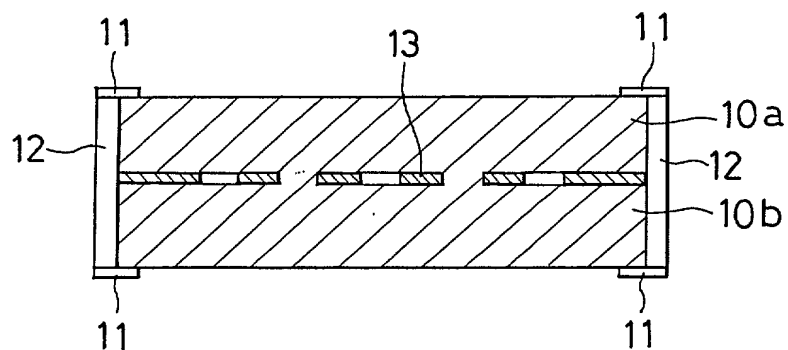


FIG. 20

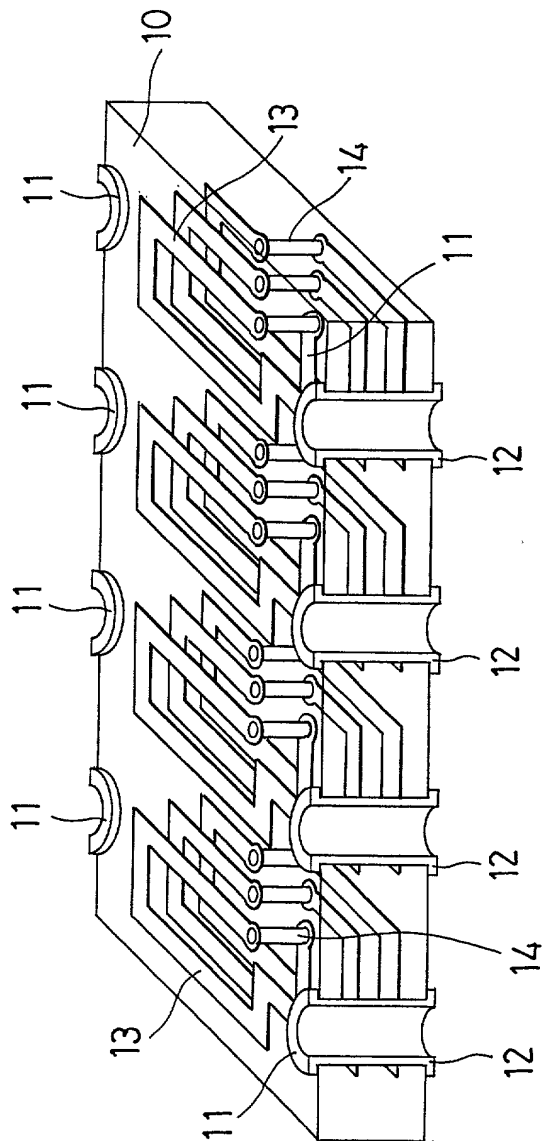


FIG. 21A

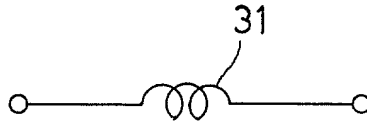


FIG. 21B

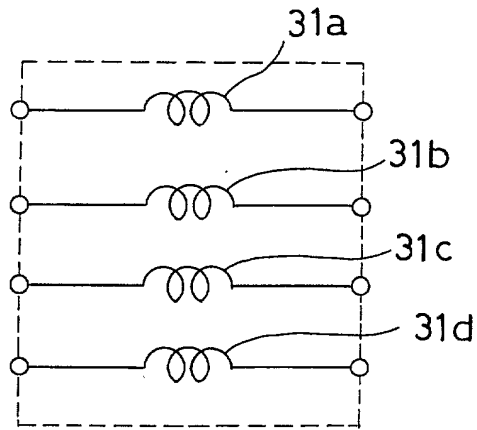


FIG. 22

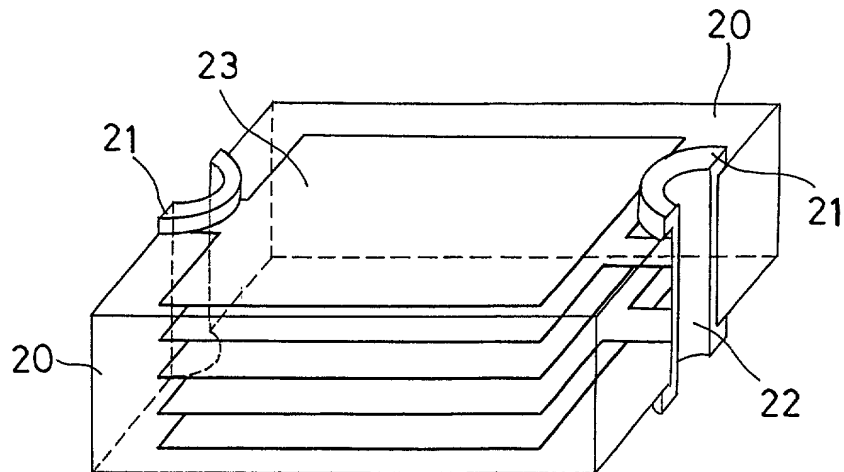
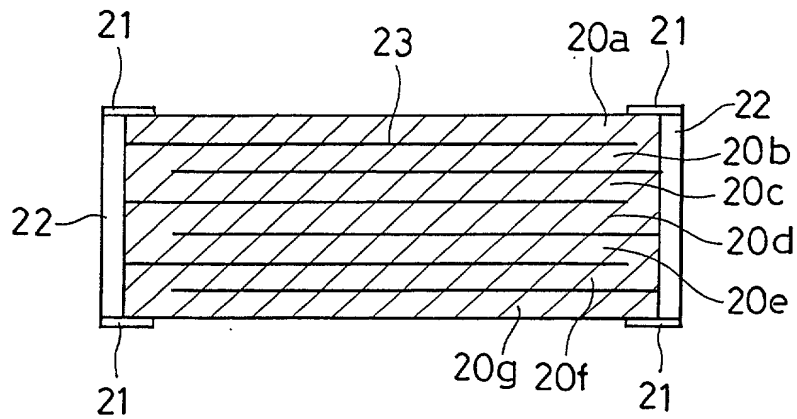


FIG. 23



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FIG. 24

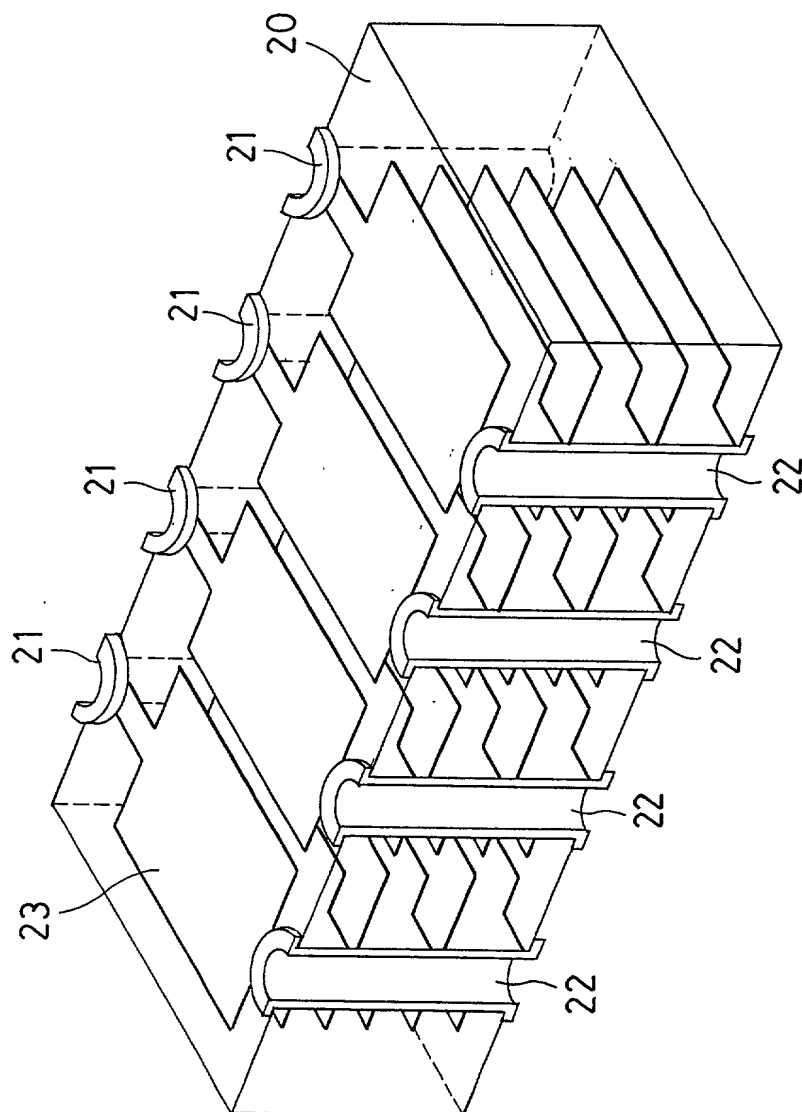


FIG. 25A

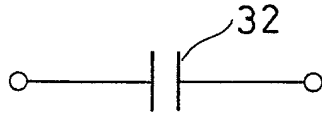


FIG. 25B

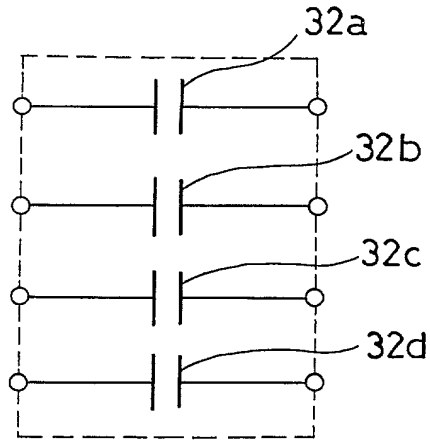


FIG. 26

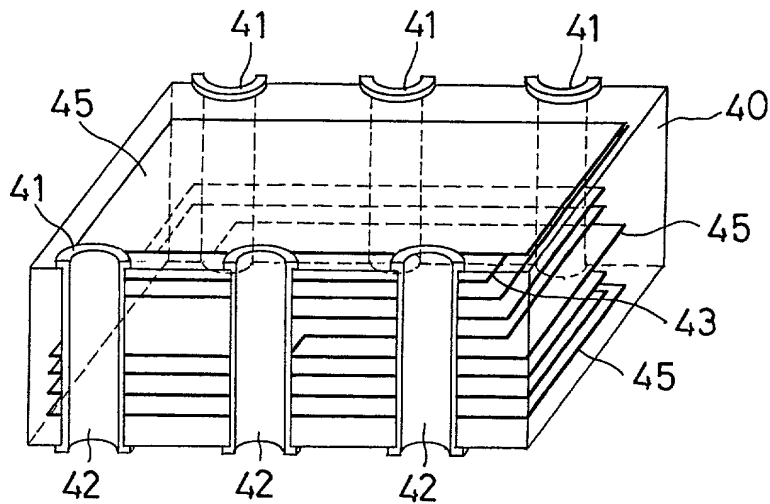
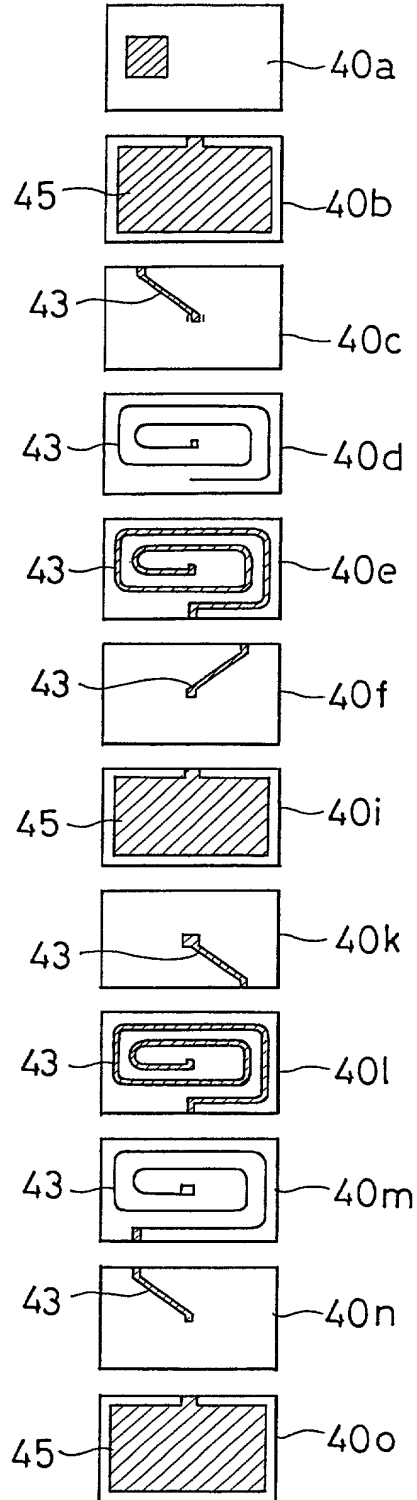
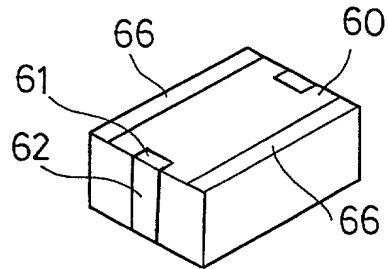


FIG. 28



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FIG. 30



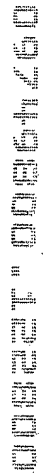
[illegible]

FIG. 32

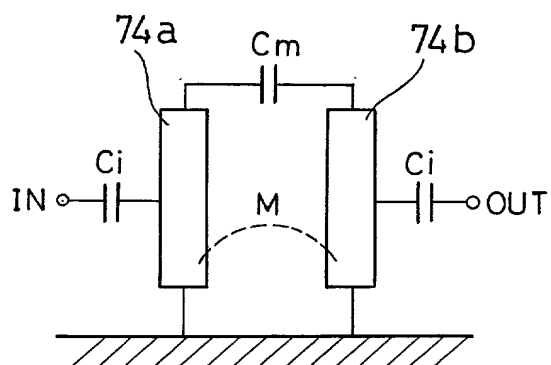


FIG. 34

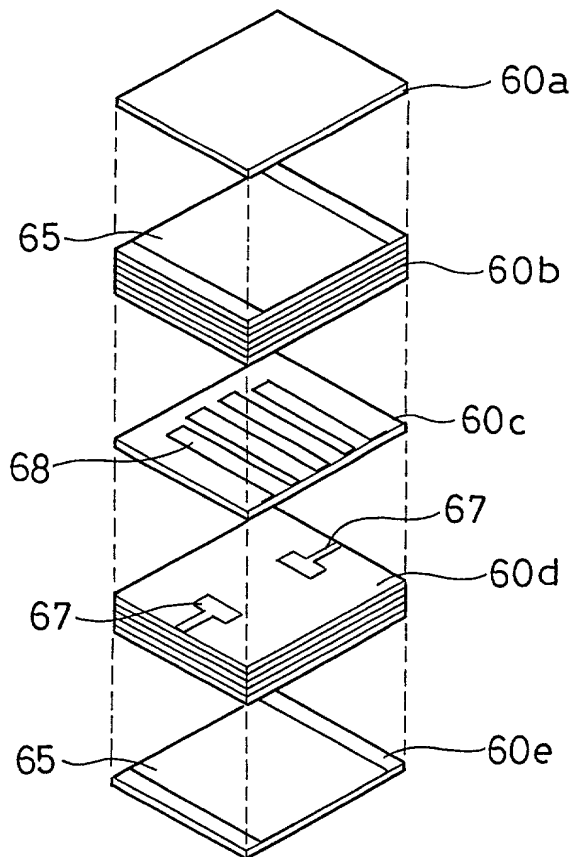
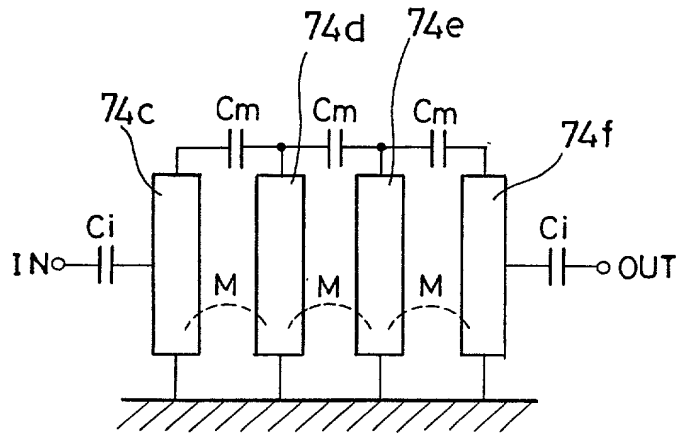


FIG. 35



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FIG. 36

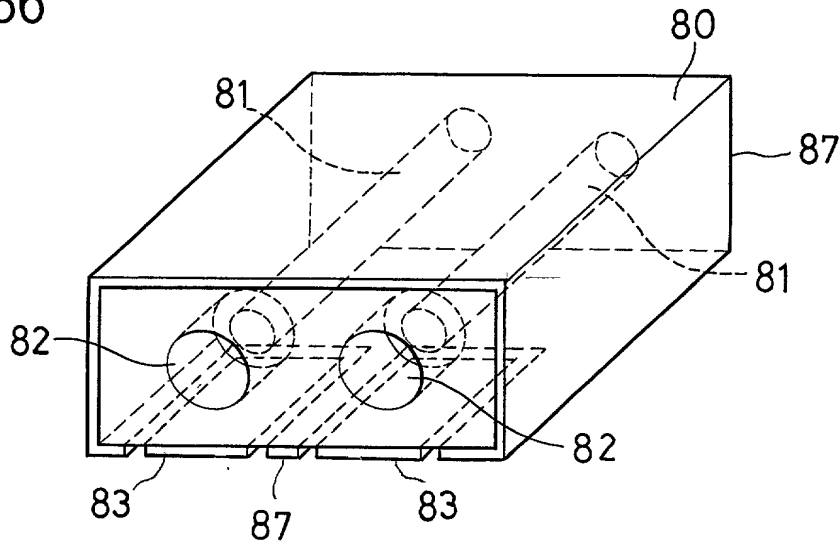


FIG. 37

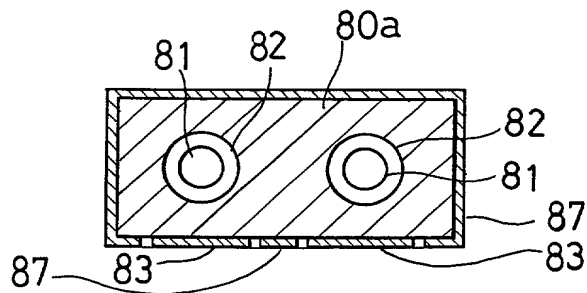


FIG. 38

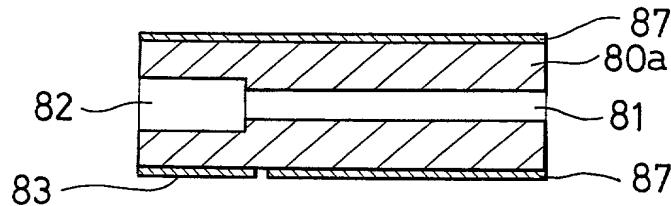
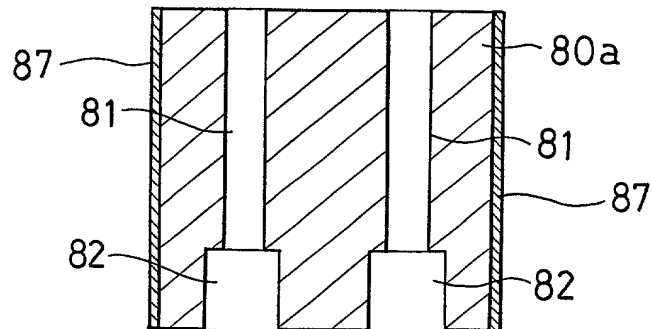


FIG. 39



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FIG. 40

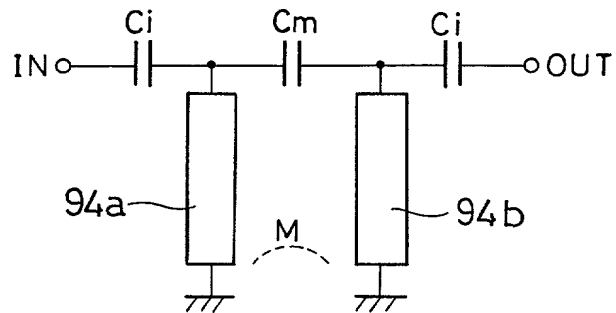


FIG. 41

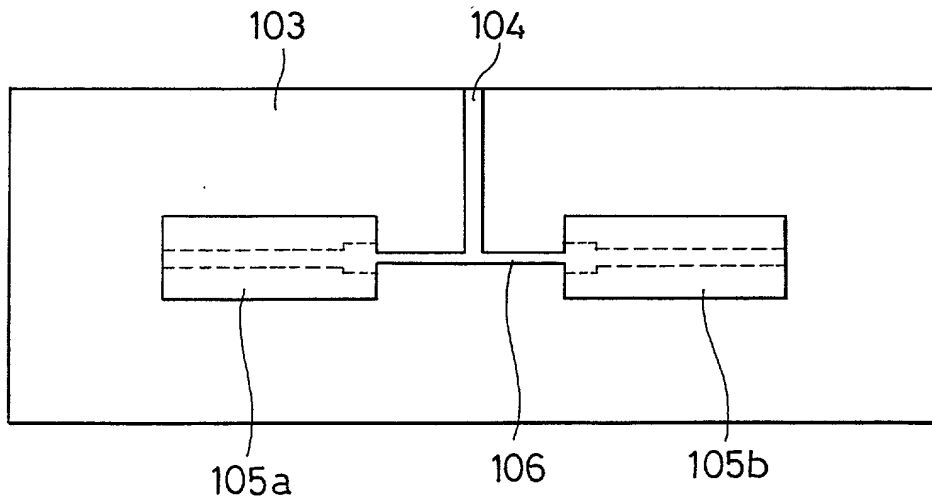


FIG. 42

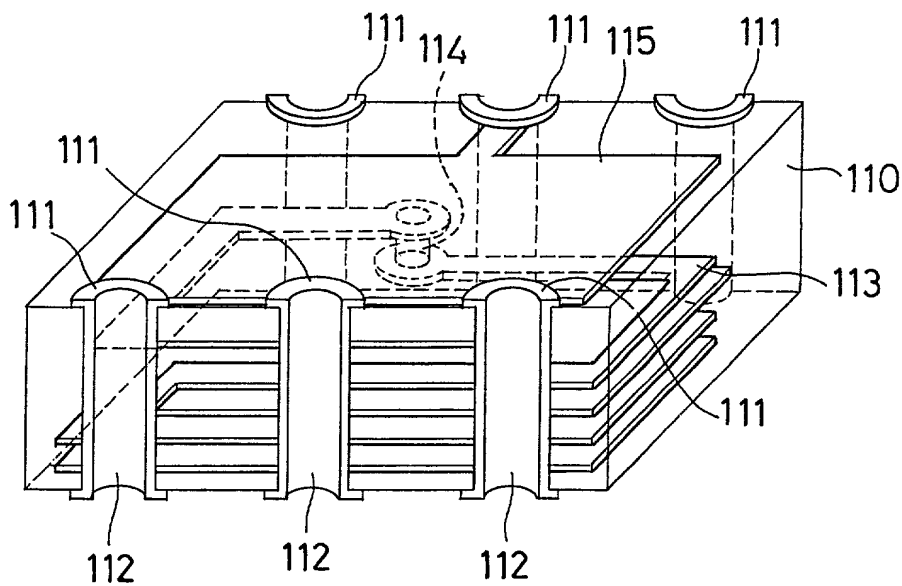


FIG. 43

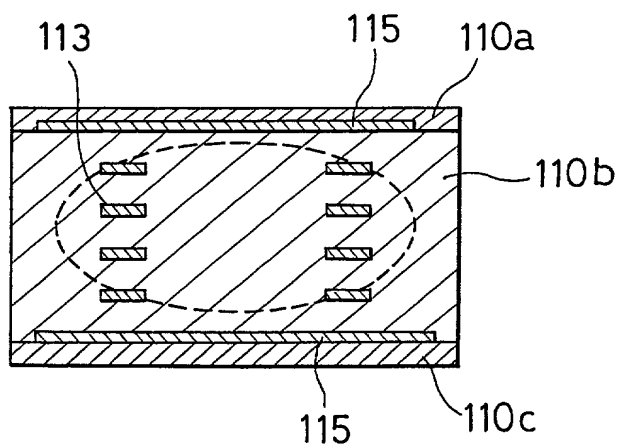
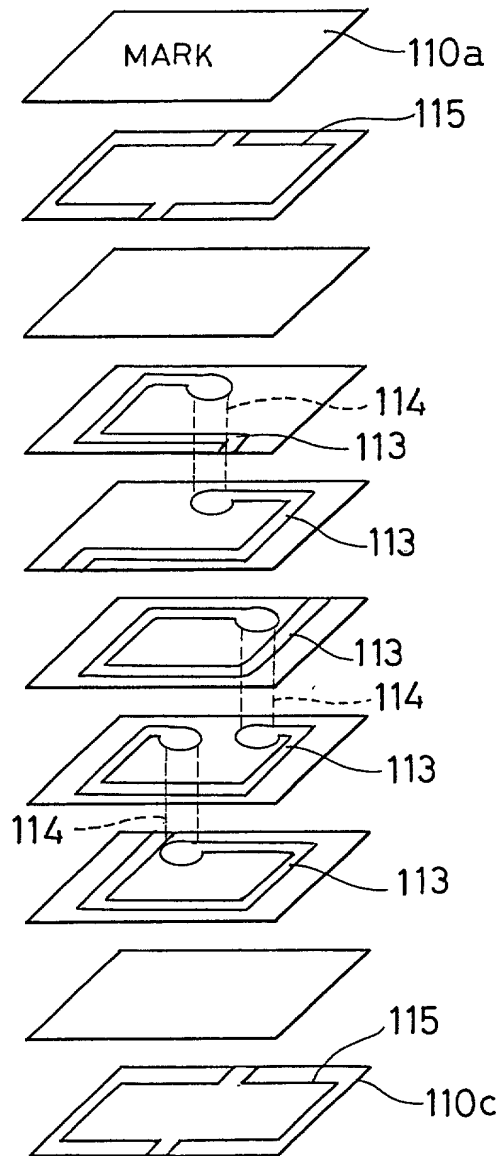


FIG. 44



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FIG. 45

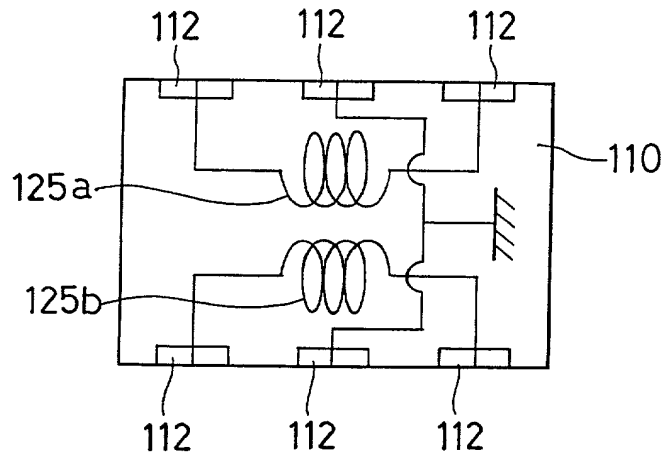
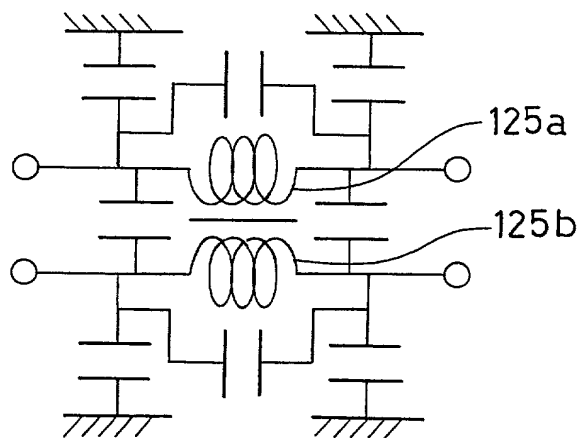


FIG. 46



008222T" 0086460

FIG. 47

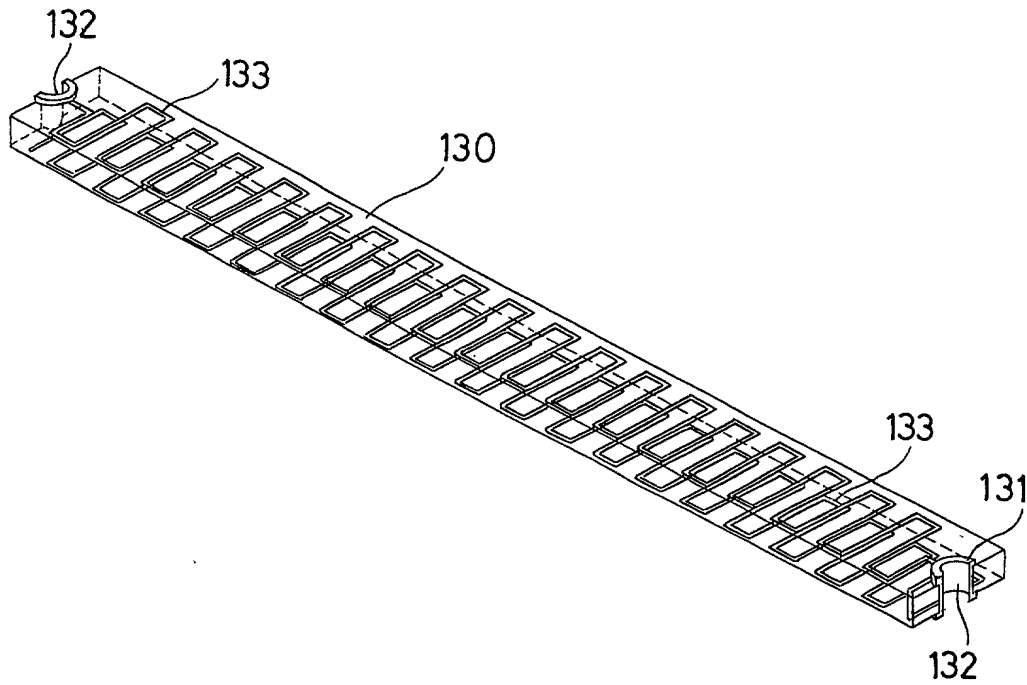


FIG. 48A

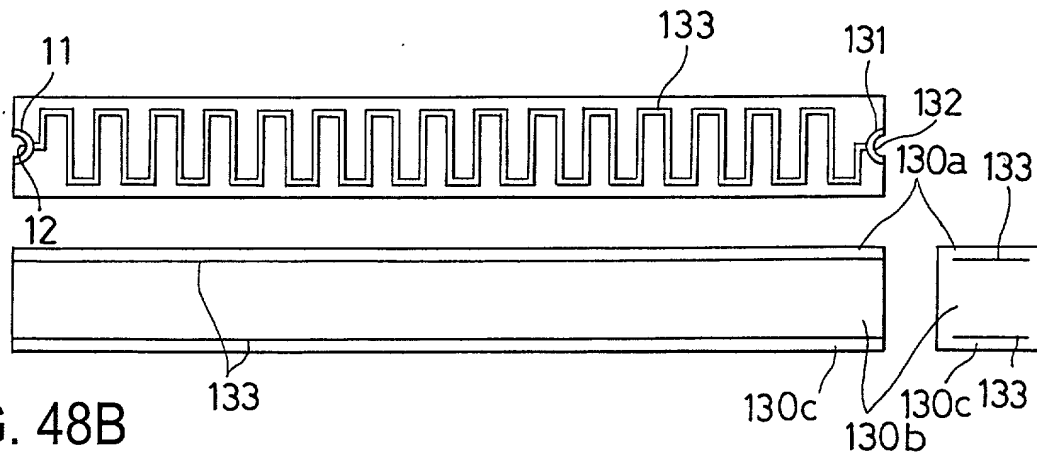
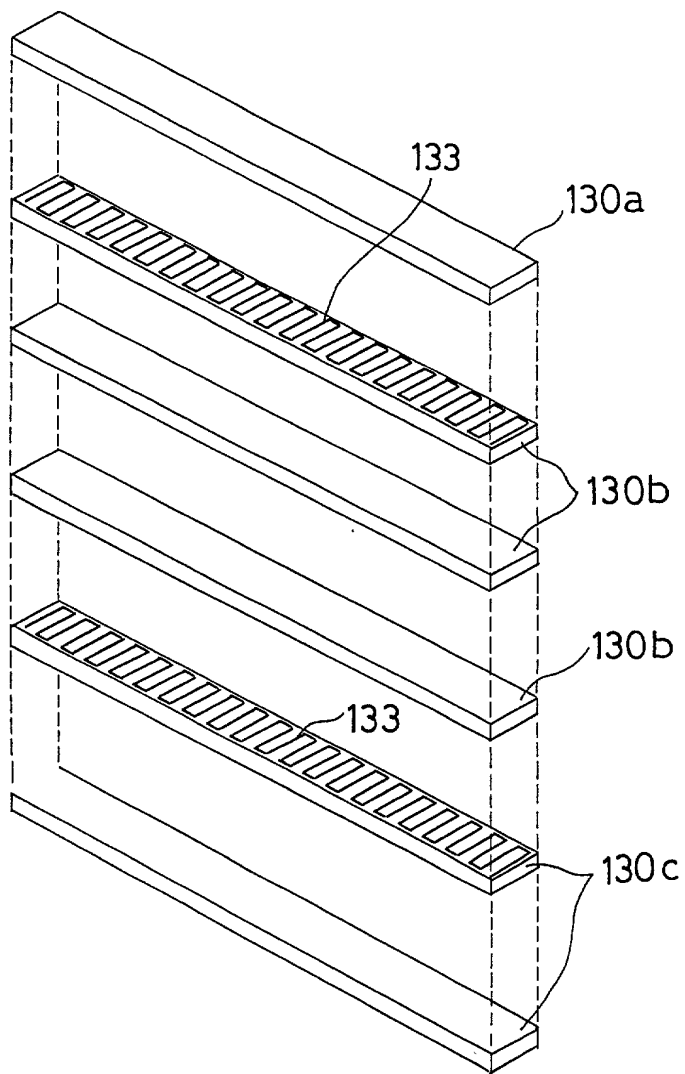


FIG. 48B

FIG. 48C

FIG. 49



008221" 00854260

FIG. 50

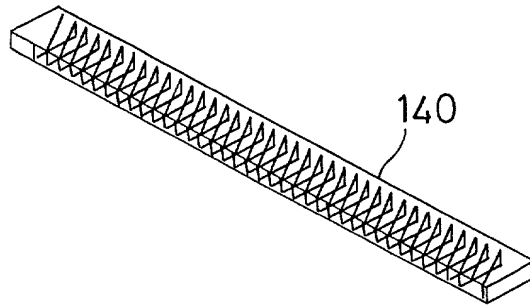


FIG. 51

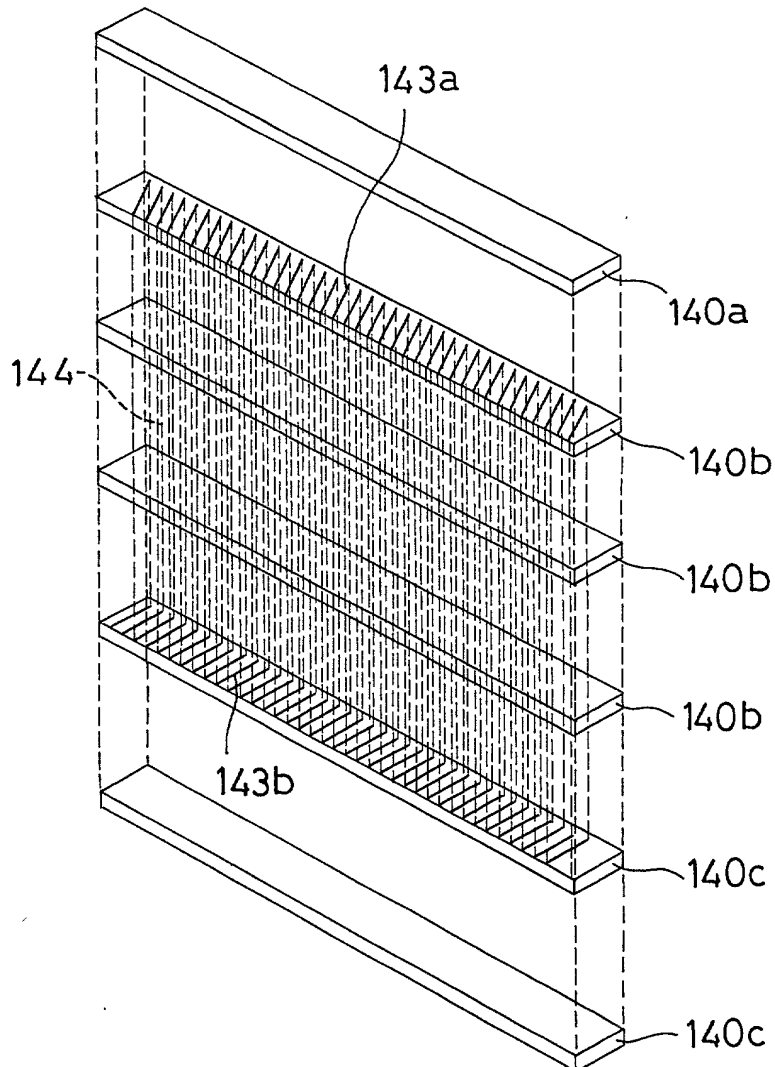


FIG. 52

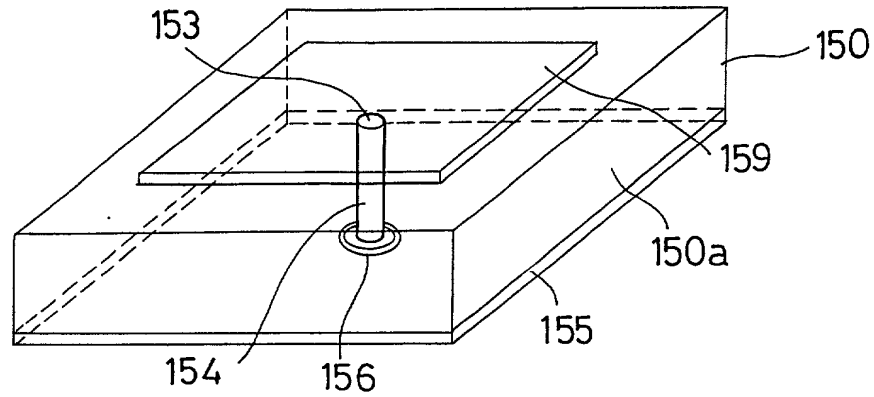


FIG. 53

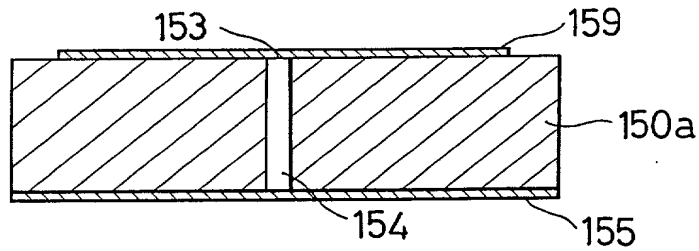


FIG. 54

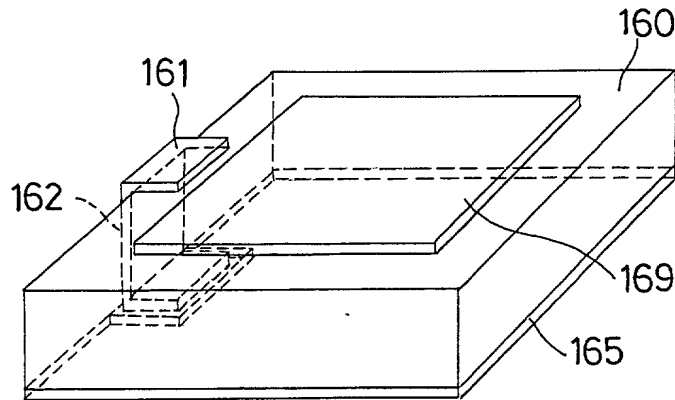


FIG. 55

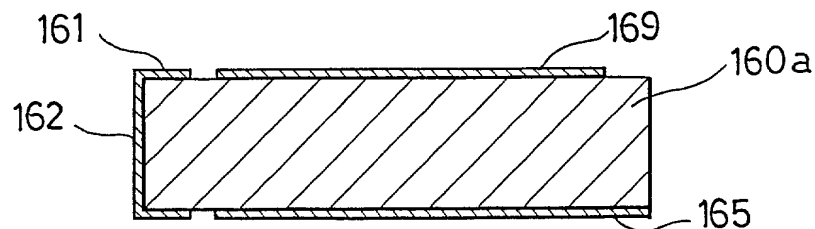


FIG. 56

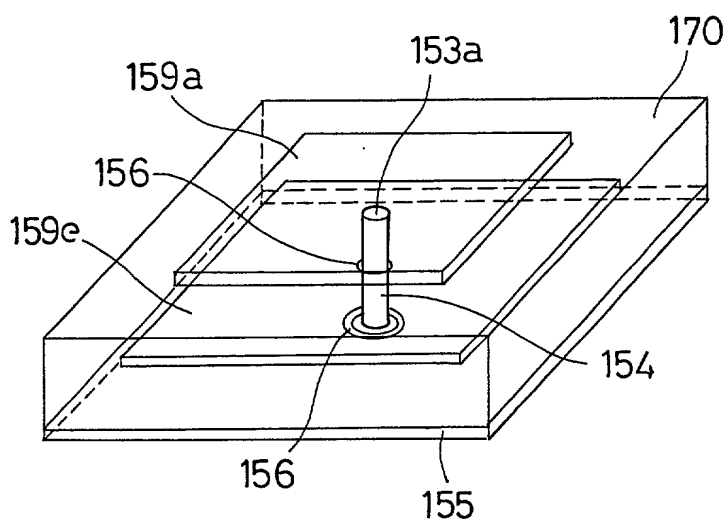


FIG. 57

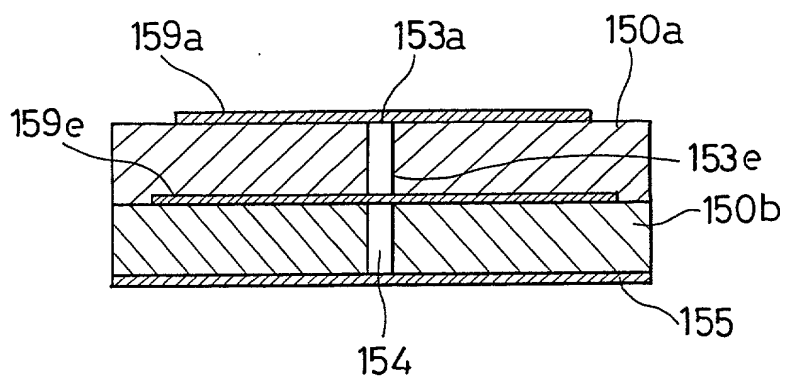


FIG. 58

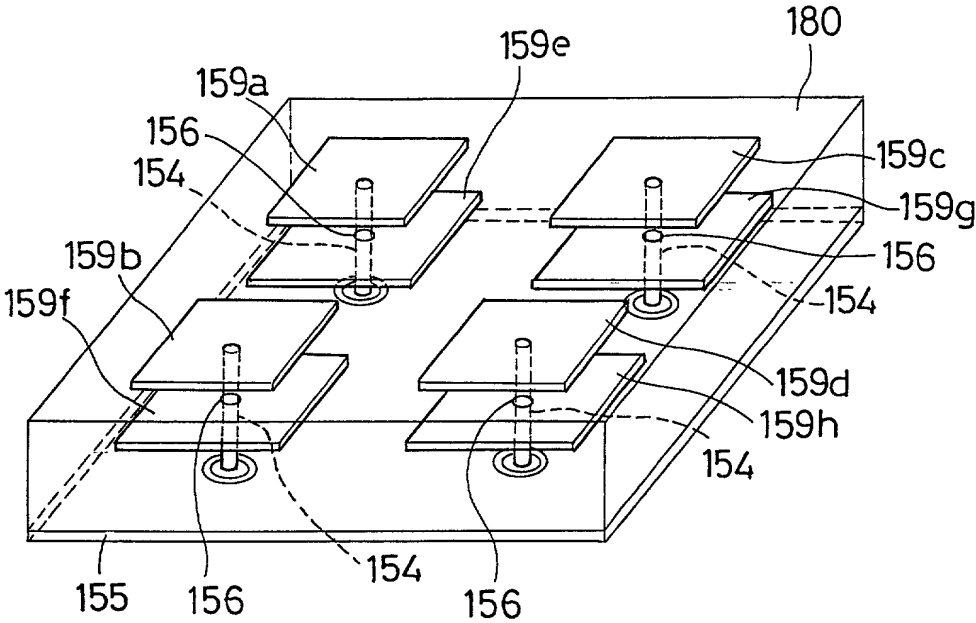


FIG. 59

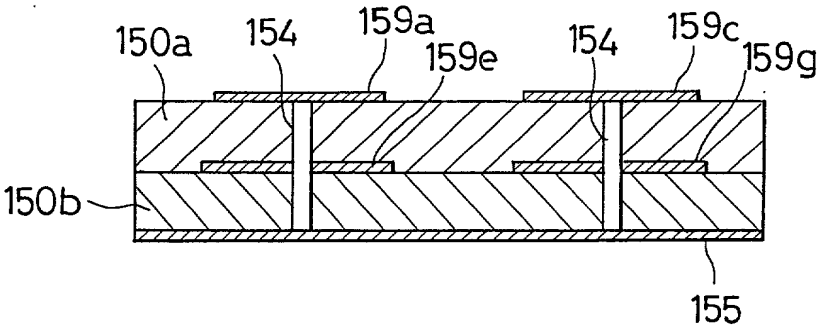


FIG. 60

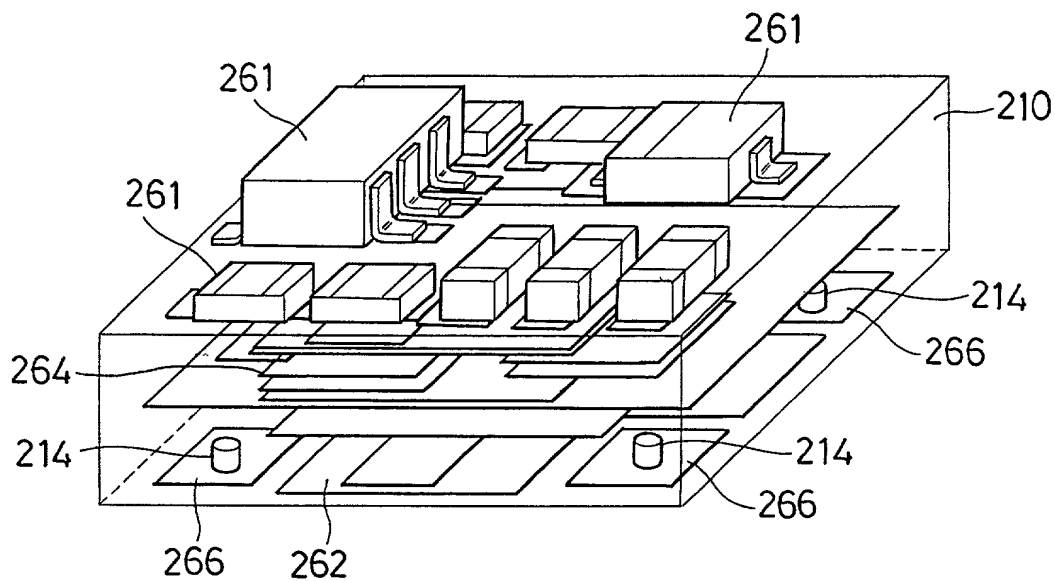


FIG. 61

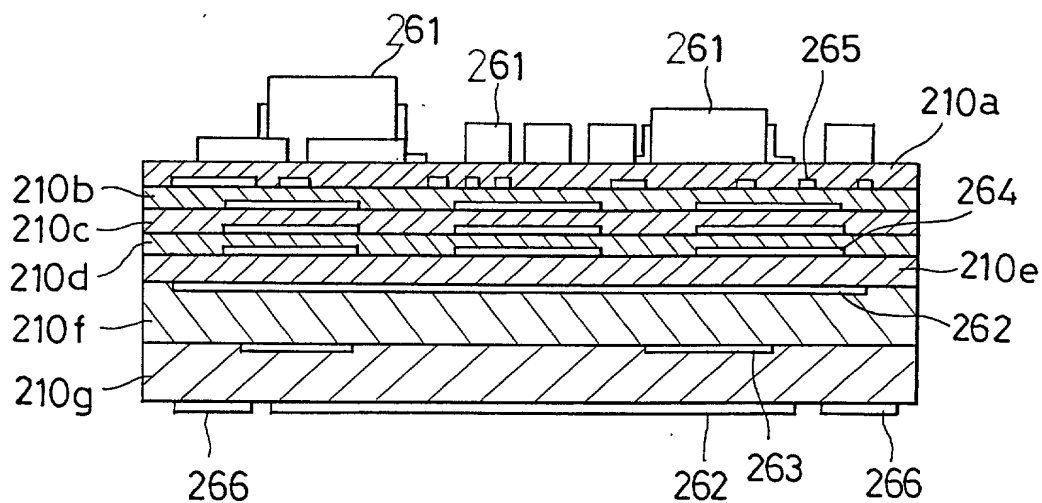


FIG. 62

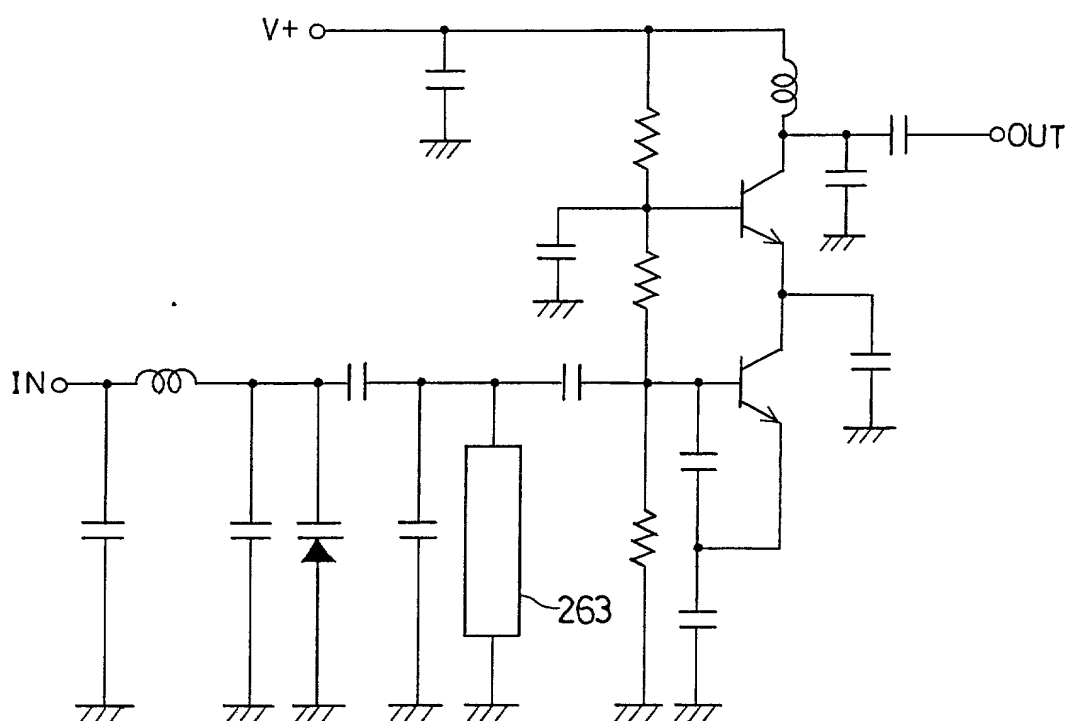


FIG. 63

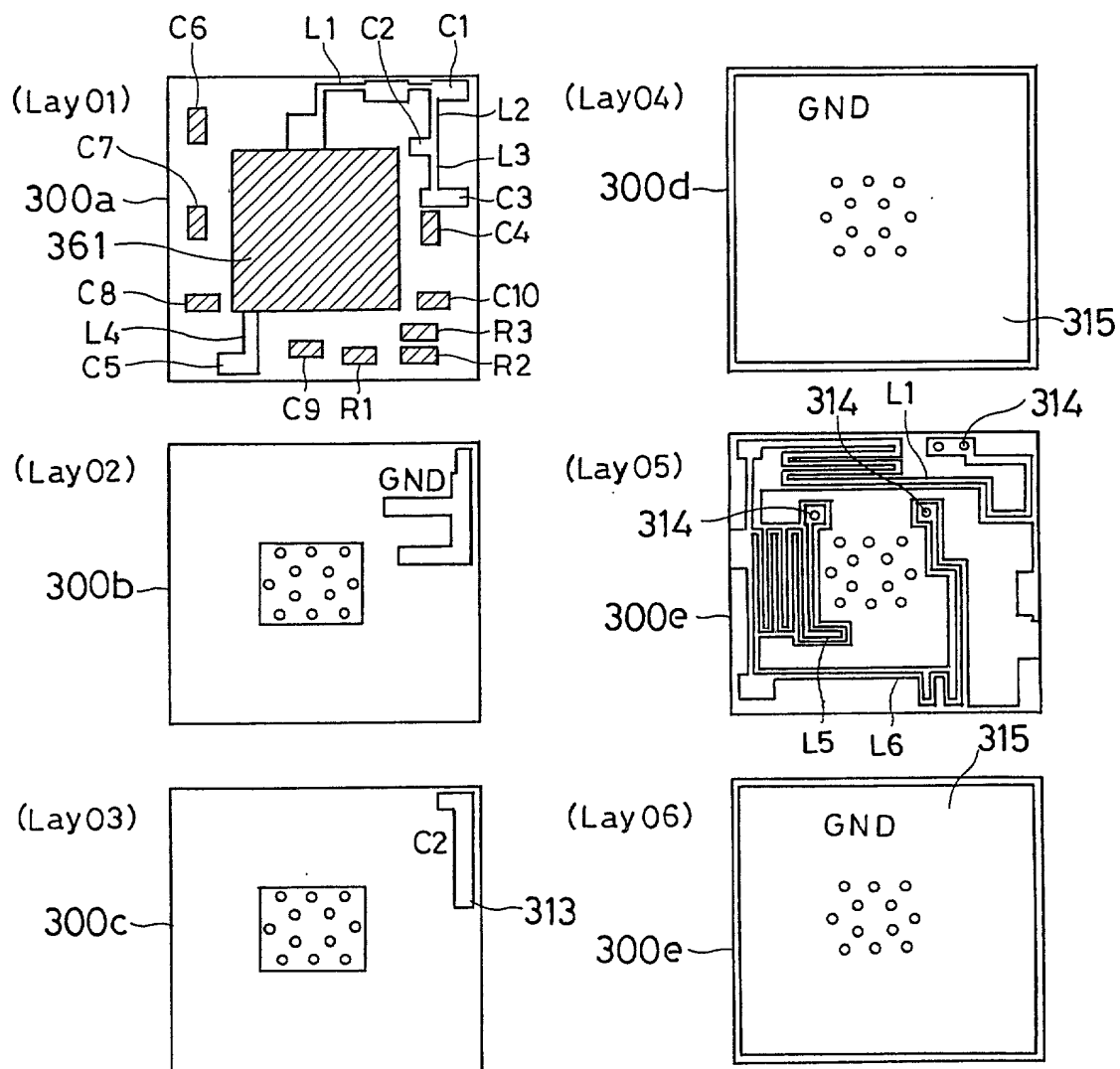


FIG. 64

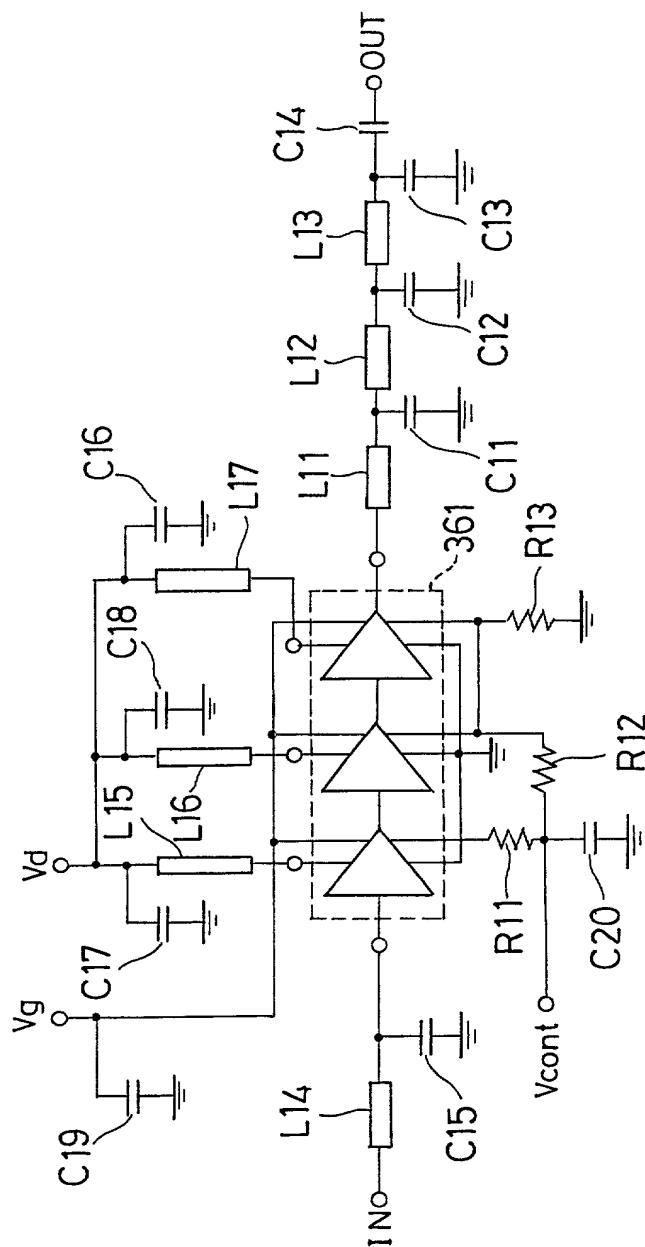


FIG. 65

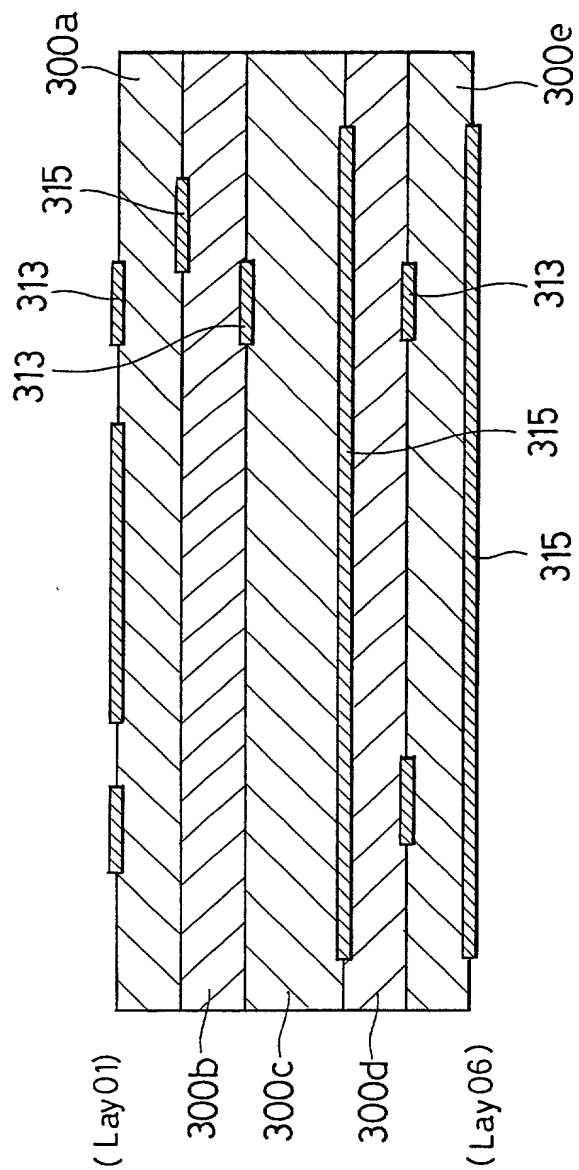


FIG. 66

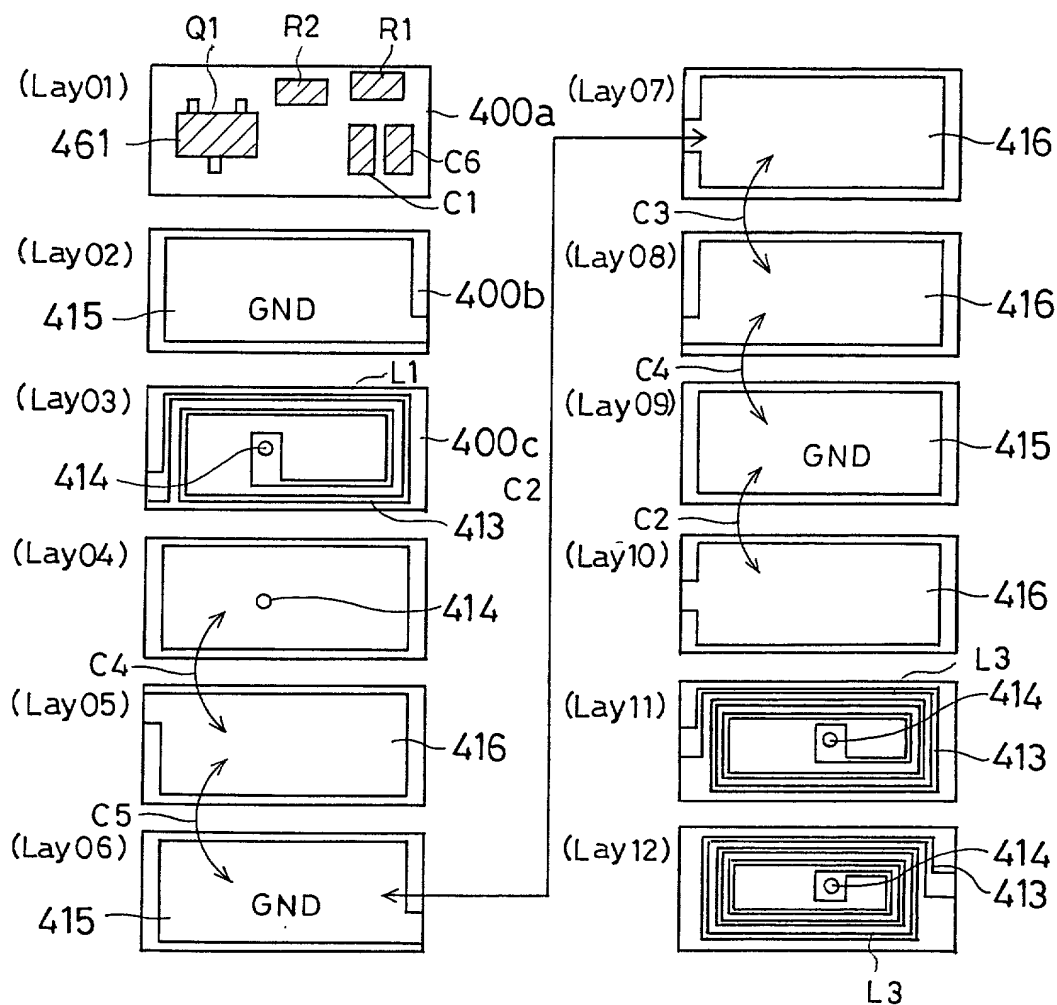


FIG. 67

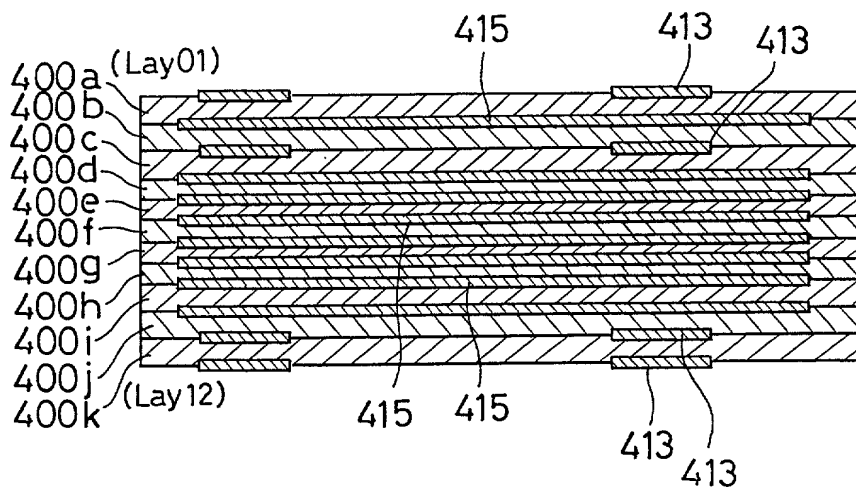


FIG. 68

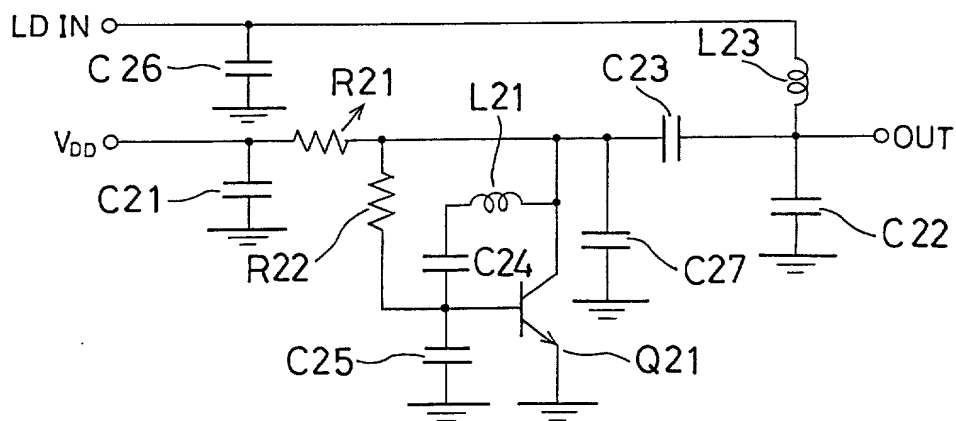
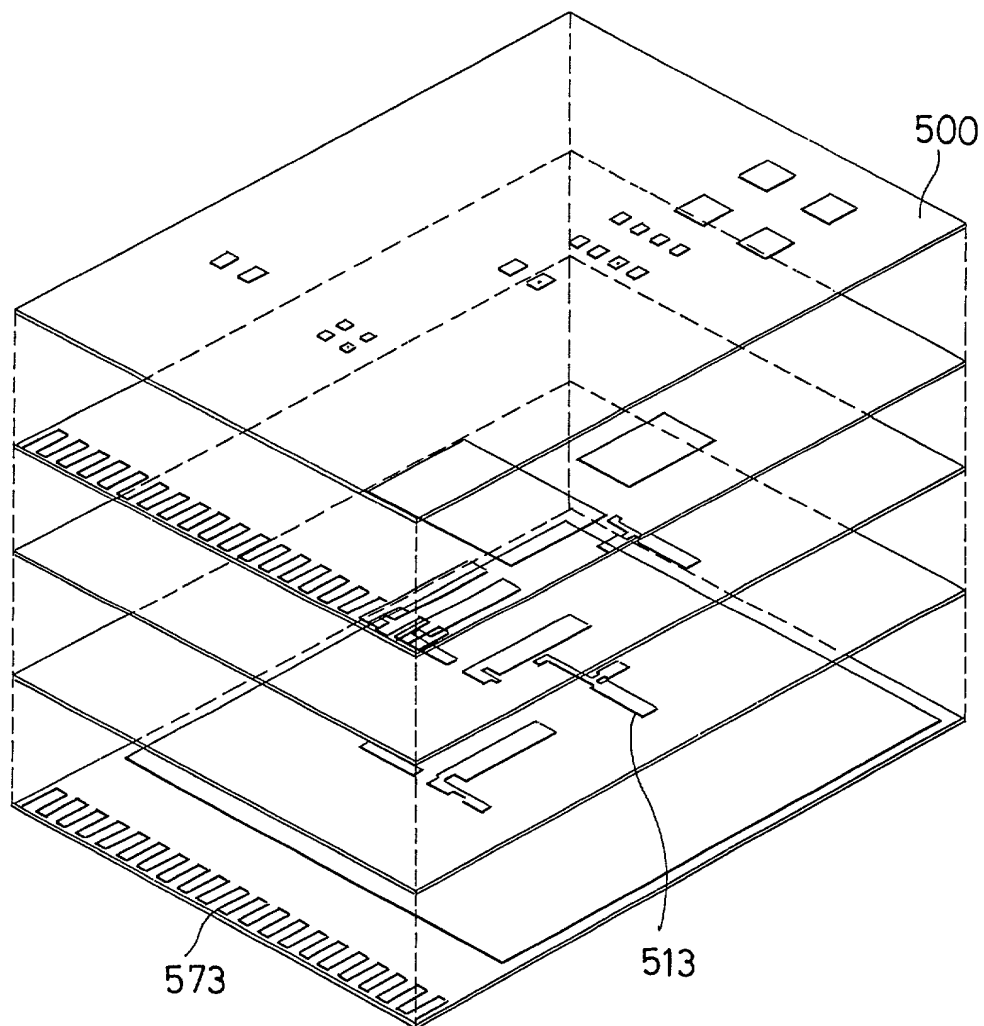


FIG. 71



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FIG. 72

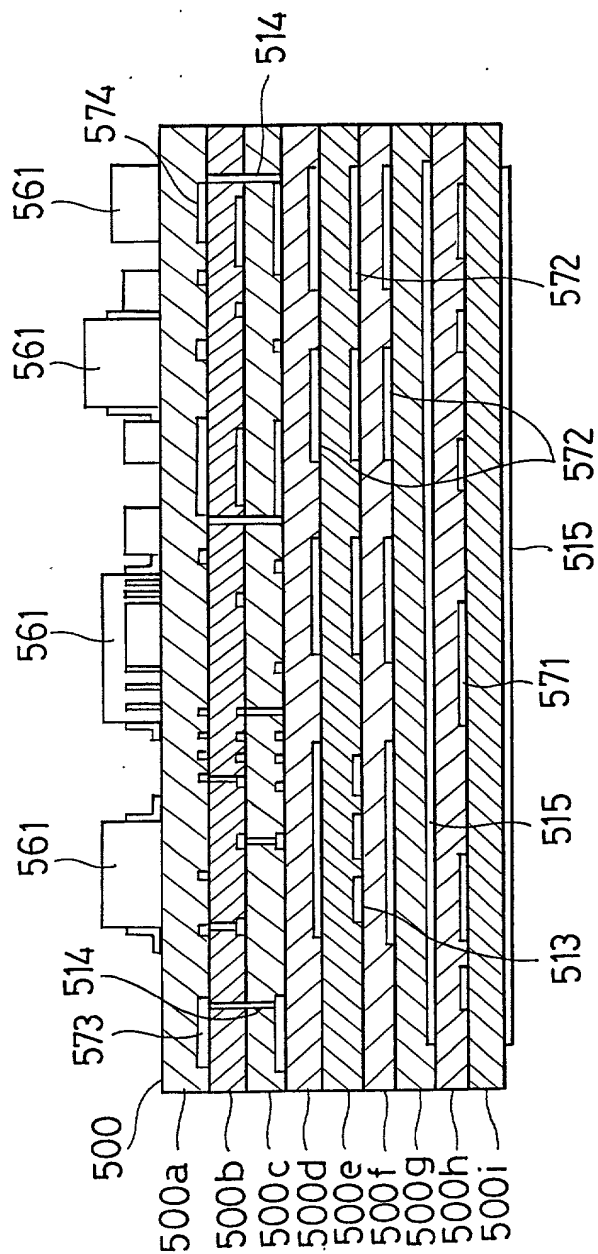


FIG. 74

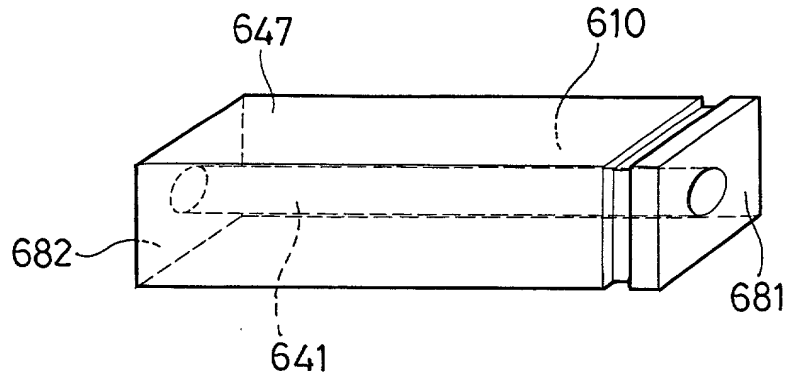


FIG. 75

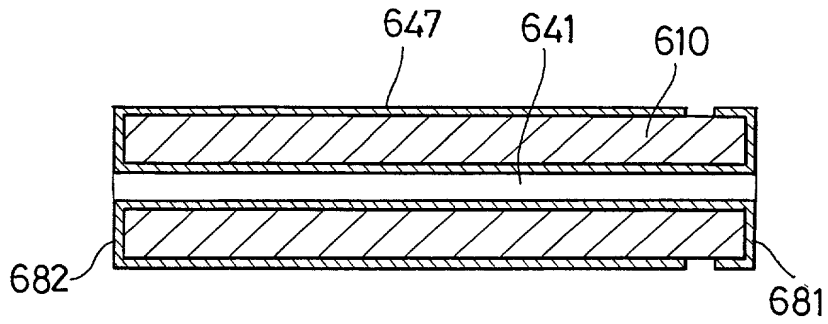


FIG. 76

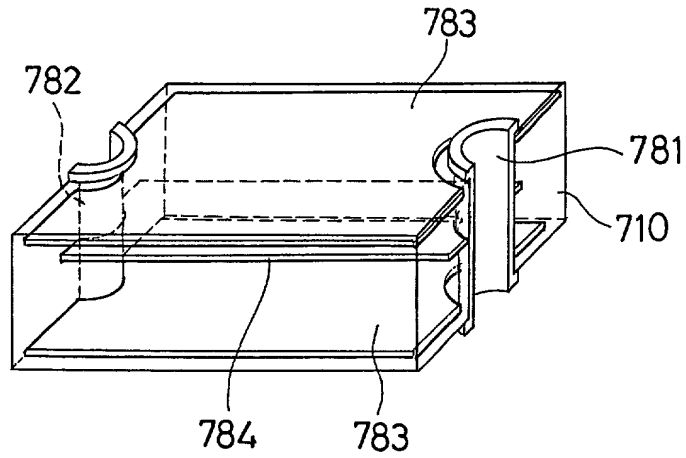


FIG. 77

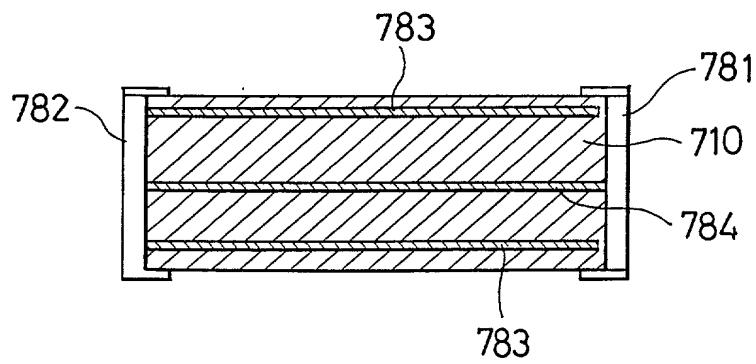


FIG. 78

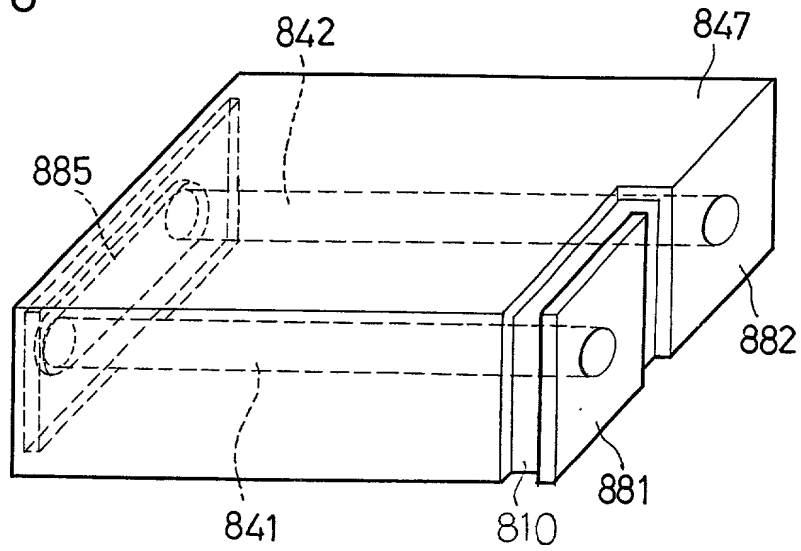


FIG. 79

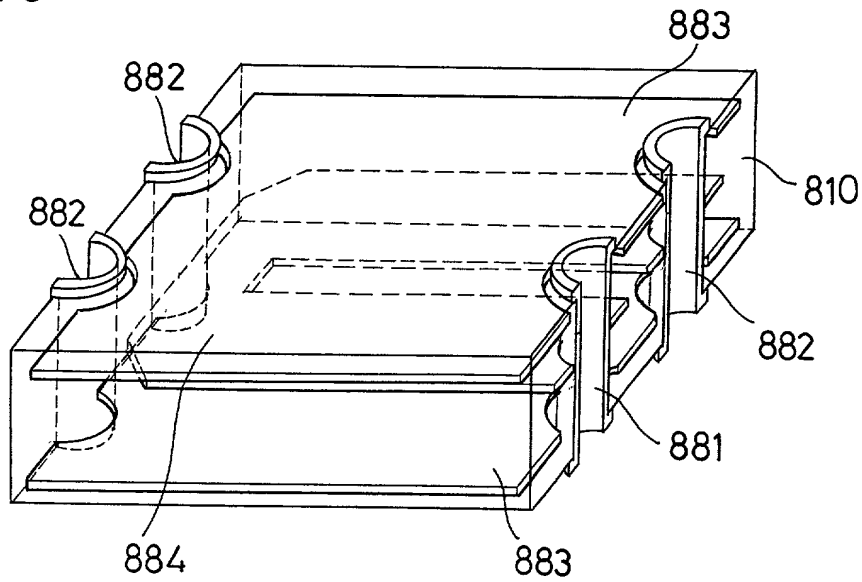


FIG. 80

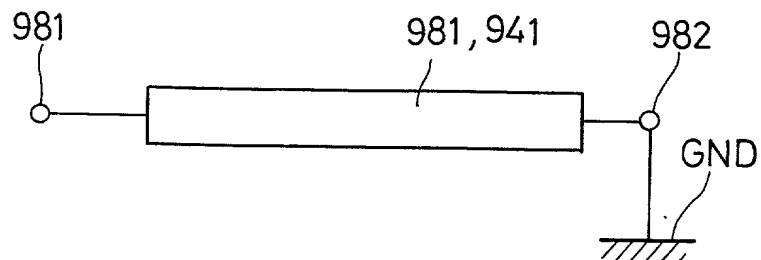


FIG. 81A

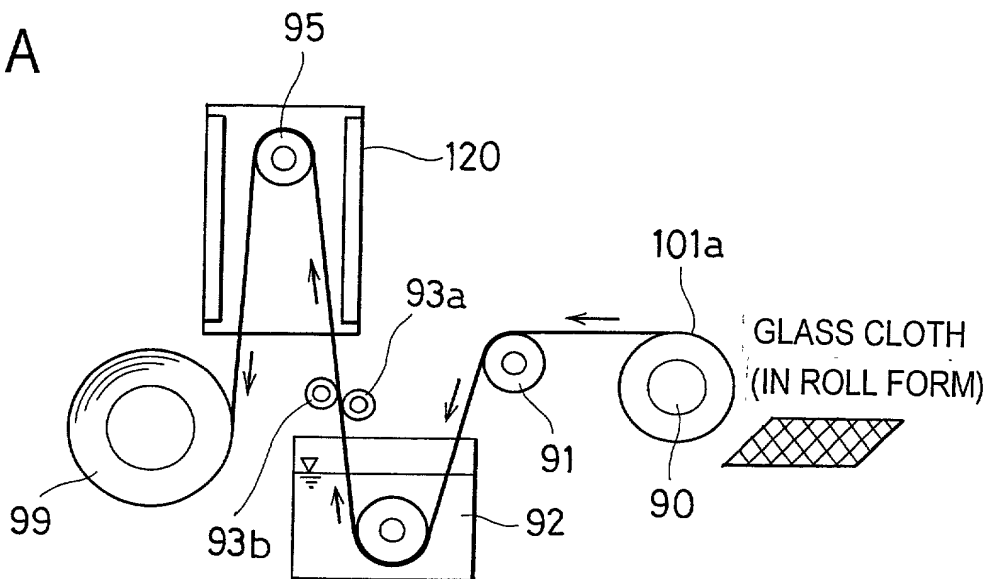


FIG. 81B

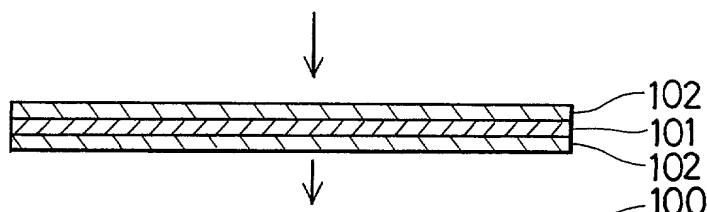


FIG. 81C

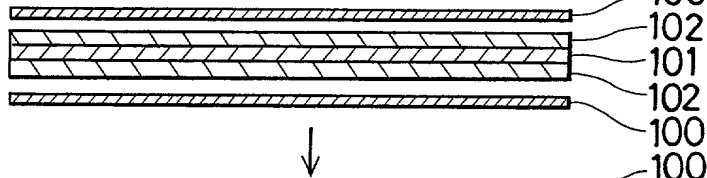


FIG. 81D

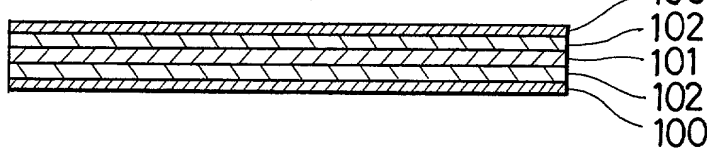
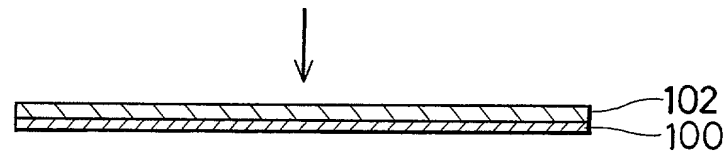
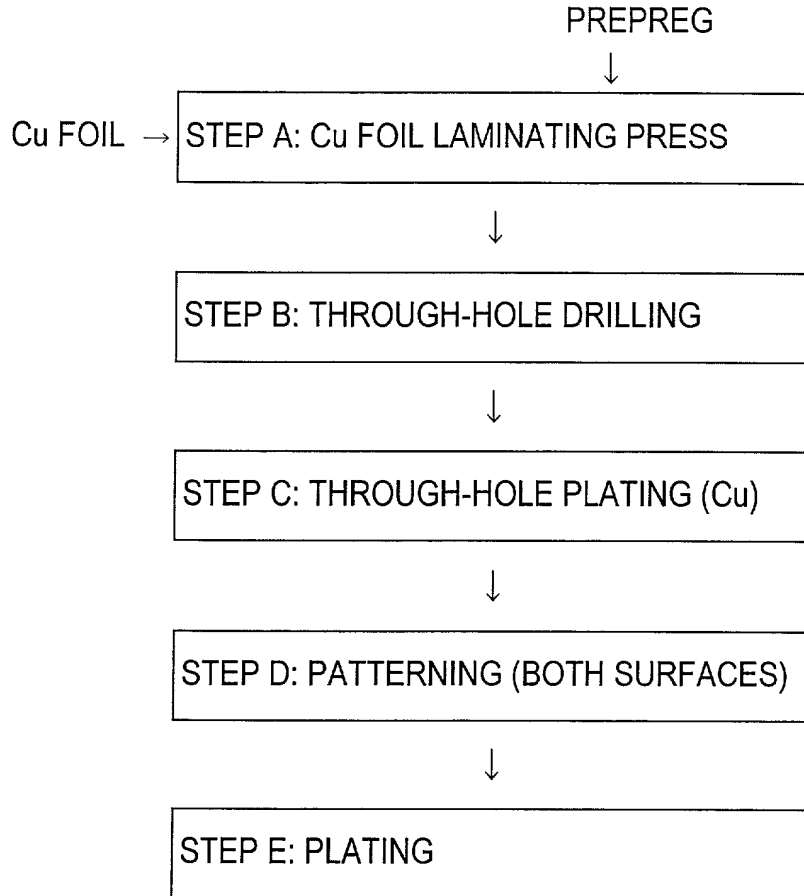


FIG. 82B



A cross-sectional view of a multilayered structure 100. The structure consists of five layers: a top layer 100, a second layer 102, a third layer 101, a fourth layer 102, and a bottom layer 100. A downward arrow indicates a pressure or force applied to the top surface of the structure.

FIG. 83



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FIG. 84

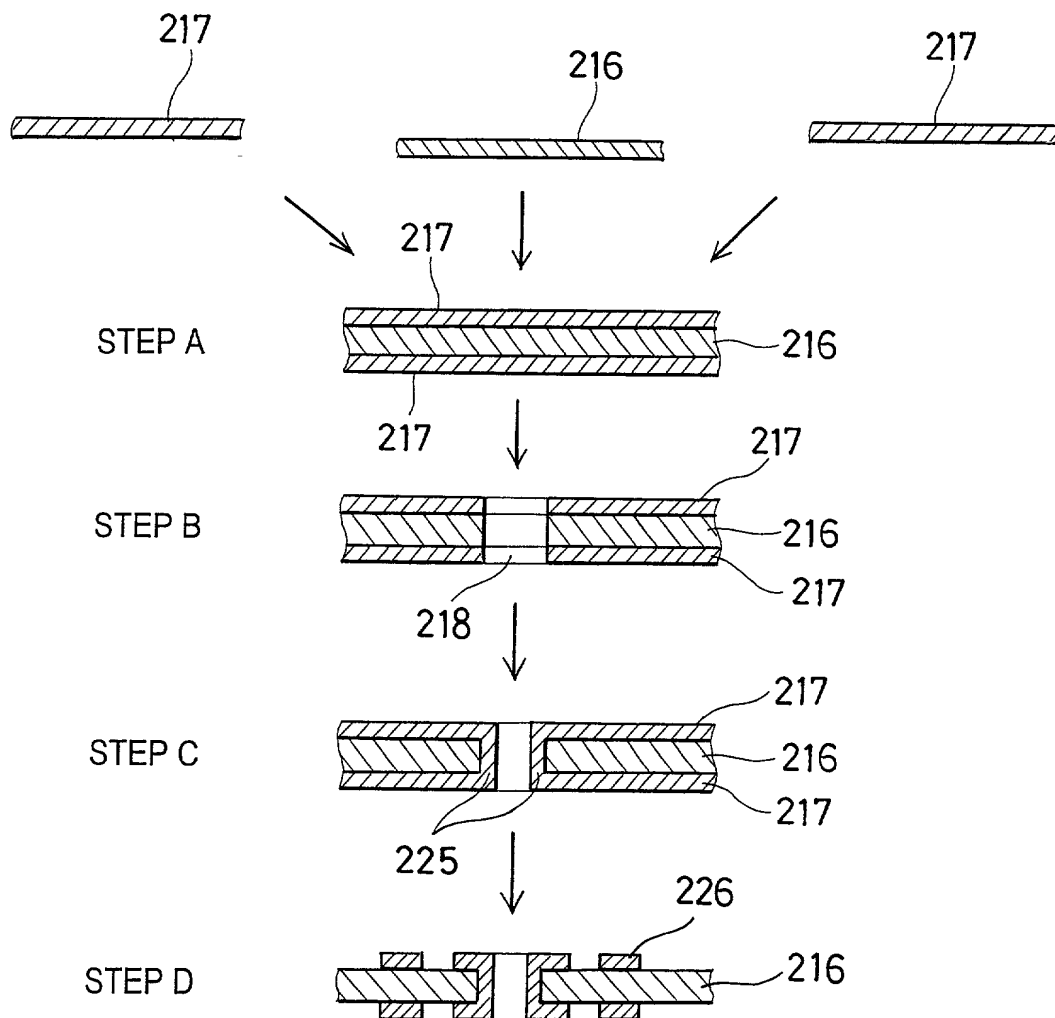
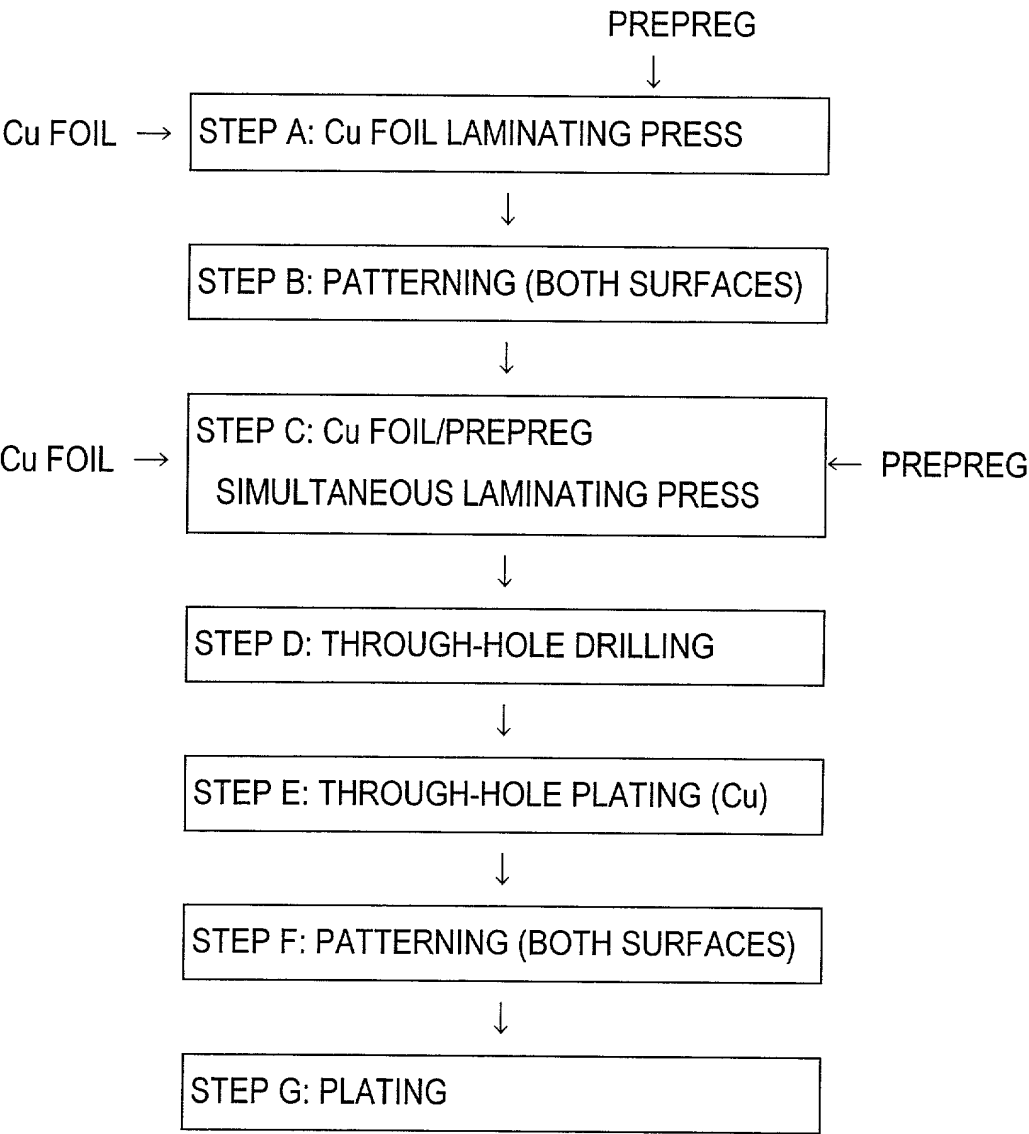


FIG. 85



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Figure 1 illustrates a manufacturing process for a semiconductor device, showing a sequence of steps from A to F:

- STEP A:** A substrate 217 is shown. A layer 216 is being deposited onto the substrate.
- STEP B:** The layer 216 is shown with openings 224.
- STEP C:** The layer 216 is shown with openings 224. A new layer 217 is being deposited onto the layer 216.
- STEP D:** The layer 216 is shown with openings 224. A new layer 217 is being deposited onto the layer 216.
- STEP E:** The layer 216 is shown with openings 224. A new layer 217 is being deposited onto the layer 216.
- STEP F:** The final structure is shown, featuring a central gap 219 and a layer 224.

FIG. 87A

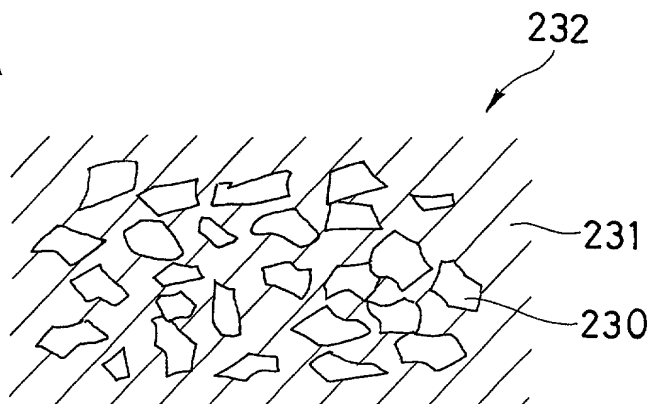


FIG. 87B

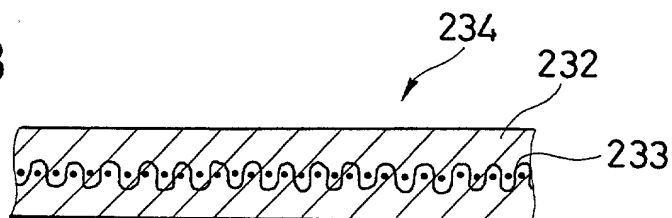


FIG. 87C

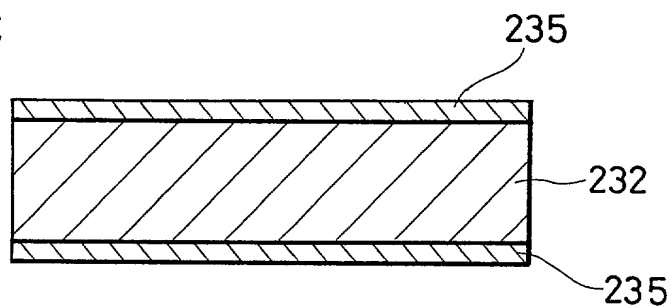


FIG. 88A

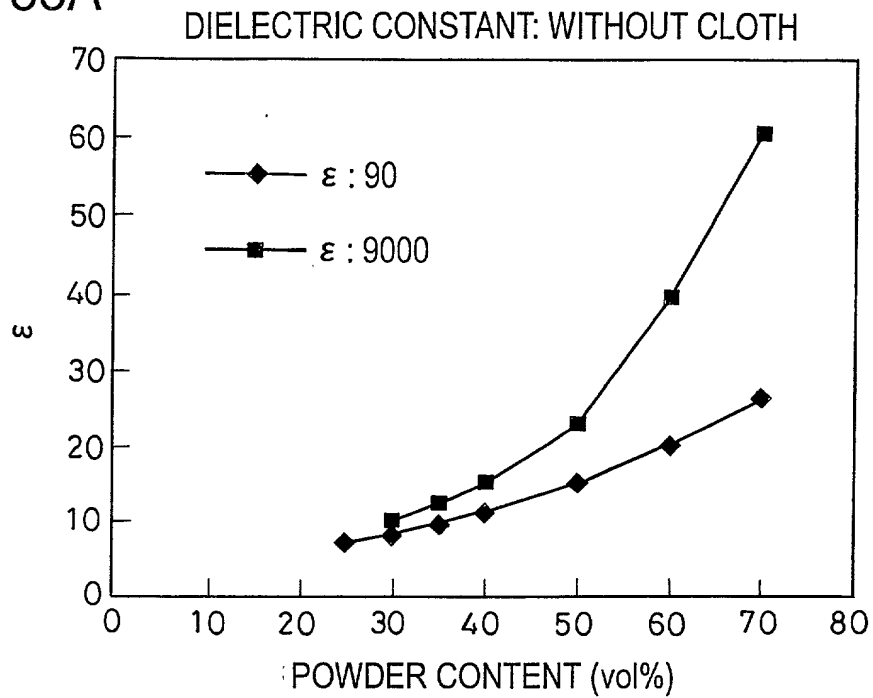


FIG. 88B

